

OPEN

Compute Project

Project Olympus
AMD EPYC™ Processor
Motherboard Specification

Author:

Fenghua Shen, Senior Hardware Engineer, Microsoft

Mark A. Shaw, Principal Hardware Engineering Manager, Microsoft

Revision History

Date	Description
11/1/17	Version 1.0

Open Compute Project • Project Olympus AMD EPYC™ Processor Motherboard Specification

© 2017 Microsoft Corporation.

As of November 1, 2017, the following persons or entities have made this Specification available under the Open Web Foundation Final Specification Agreement (OWFa 1.0), which is available at <http://www.openwebfoundation.org/legal/the-owf-1-0-agreements/owfa-1-0>

Microsoft Corporation.

You can review the signed copies of the Open Web Foundation Agreement Version 1.0 for this Specification at [Project Olympus License Agreements](#), which may also include additional parties to those listed above.

Your use of this Specification may be subject to other third party rights. THIS SPECIFICATION IS PROVIDED "AS IS." The contributors expressly disclaim any warranties (express, implied, or otherwise), including implied warranties of merchantability, non-infringement, fitness for a particular purpose, or title, related to the Specification. The entire risk as to implementing or otherwise using the Specification is assumed by the Specification implementer and user. IN NO EVENT WILL ANY PARTY BE LIABLE TO ANY OTHER PARTY FOR LOST PROFITS OR ANY FORM OF INDIRECT, SPECIAL, INCIDENTAL, OR CONSEQUENTIAL DAMAGES OF ANY CHARACTER FROM ANY CAUSES OF ACTION OF ANY KIND WITH RESPECT TO THIS SPECIFICATION OR ITS GOVERNING AGREEMENT, WHETHER BASED ON BREACH OF CONTRACT, TORT (INCLUDING NEGLIGENCE), OR OTHERWISE, AND WHETHER OR NOT THE OTHER PARTY HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGE.

CONTRIBUTORS AND LICENSORS OF THIS SPECIFICATION MAY HAVE MENTIONED CERTAIN TECHNOLOGIES THAT ARE MERELY REFERENCED WITHIN THIS SPECIFICATION AND NOT LICENSED UNDER THE OWF CLA OR OWFa. THE FOLLOWING IS A LIST OF MERELY REFERENCED TECHNOLOGY: INTELLIGENT PLATFORM MANAGEMENT INTERFACE (IPMI); I²C IS A TRADEMARK AND TECHNOLOGY OF NXP SEMICONDUCTORS ; EPYC IS A TRADEMARK AND TECHNOLOGY OF ADVANCED MICRO DEVICES INC.; ASPEED AST 2400/2500 FAMILY PROCESSORS IS A TECHNOLOGY OF ASPEED TECHNOLOGY INC.; MOLEX NANOPITCH, NANO PICOBLADE, AND MINI-FIT JR AND ASSOCIATED CONNECTORS ARE TRADEMARKS AND TECHNOLOGIES OF MOLEX LLC; WINBOND IS A TRADEMARK OF WINBOND ELECTRONICS CORPORATION; NVLINK IS A TECHNOLOGY OF NVIDIA; INTEL XEON SCALABLE PROCESSORS, INTEL QUICKASSIST TECHNOLOGY, INTEL HYPER-THREADING TECHNOLOGY, ENHANCED INTEL SPEEDSTEP TECHNOLOGY, INTEL VIRTUALIZATION TECHNOLOGY, INTEL SERVER PLATFORM SERVICES, INTEL MANAGABILITY ENGINE, AND INTEL TRUSTED EXECUTION TECHNOLOGY ARE TRADEMARKS AND TECHNOLOGIES OF INTEL CORPORATION; SITARA ARM CORTEX-A9 PROCESSOR IS A TRADEMARK AND TECHNOLOGY OF TEXAS INSTRUMENTS; GUIDE PINS FROM PENCOM; BATTERIES FROM PANASONIC. IMPLEMENTATION OF THESE TECHNOLOGIES MAY BE SUBJECT TO THEIR OWN LEGAL TERMS.

Contents

1	Project Olympus Specifications List	1
2	Overview	1
3	Background	2
4	Block Diagram	2
5	Features	3
5.1	<i>CPUs</i>	<i>4</i>
5.2	<i>DIMMs.....</i>	<i>4</i>
5.3	<i>PCIe Support.....</i>	<i>5</i>
5.3.1	<i>CPU PCIe Mapping</i>	<i>5</i>
5.3.2	<i>PCIe x8 Slots.....</i>	<i>5</i>
5.3.3	<i>PCIe x16/32 Slots</i>	<i>5</i>
5.3.4	<i>PCIe Cables.....</i>	<i>6</i>
5.3.5	<i>M.2 Modules.....</i>	<i>6</i>
5.4	<i>PCIe/SATA Expansion</i>	<i>6</i>
5.5	<i>SATA Storage.....</i>	<i>6</i>
5.6	<i>TPM Module.....</i>	<i>6</i>
6	Management Subsystem	7
6.1	<i>BMC.....</i>	<i>8</i>
6.2	<i>BMC DRAM.....</i>	<i>8</i>
6.3	<i>BMC Boot Flash</i>	<i>8</i>
6.4	<i>BIOS Flash.....</i>	<i>8</i>
6.5	<i>1GbE PHY.....</i>	<i>8</i>
6.6	<i>UARTs.....</i>	<i>9</i>
6.7	<i>VGA</i>	<i>9</i>
6.8	<i>I2C</i>	<i>9</i>
6.8.1	<i>FRUID PROM</i>	<i>11</i>
6.8.2	<i>Temperature Sensors.....</i>	<i>11</i>
6.8.3	<i>PCIe Devices.....</i>	<i>12</i>
6.8.4	<i>Voltage Regulators.....</i>	<i>12</i>
6.8.5	<i>Hot Swap Controllers</i>	<i>12</i>
6.8.6	<i>Clock Buffers</i>	<i>12</i>
6.9	<i>JTAG</i>	<i>12</i>
6.10	<i>Jumpers</i>	<i>13</i>

Open Compute Project • Project Olympus AMD EPYC™ Processor Motherboard Specification

6.11	LEDs.....	13
6.11.1	UID LED.....	14
6.11.2	Power Status LED.....	14
6.11.3	Attention LED.....	15
6.11.4	PSU Status LEDs.....	15
6.12	Fan Control.....	15
7	Power Management.....	15
7.1	Rack Management.....	16
7.2	PSU Management.....	17
7.3	Hot Swap Controller.....	18
7.4	Power Capping.....	18
7.5	PWRBRK#.....	19
7.6	MEM VRHOT and EVENT_L.....	19
8	Motherboard Layout.....	20
9	Serviceability.....	22
9.1	Debug features.....	22
9.2	LED Visibility.....	22
10	Motherboard Interfaces.....	22
10.1	PCIe x8 Connectors.....	23
10.2	PCIe x16 Connectors.....	25
10.3	PCIe x32 Connector.....	27
10.4	PCIe MiniSAS HD Connectors.....	31
10.5	M.2 Connectors.....	32
10.6	SATA Cable Ports.....	33
10.7	SATA Power Connector.....	33
10.8	SATA Power Expansion Connector.....	34
10.9	12V Power Connector.....	35
10.10	Management Connector.....	36
10.11	Management Expansion Connector.....	37
10.12	OCuLink x8 Connector.....	37
10.13	NCSI Connector.....	39
10.14	USB 2.0 Internal Header.....	40
10.15	Fan Control Connector.....	41
10.16	TPM Connector.....	42



10.17	Connector Quality	43
11	Electrical Specifications	43
11.1	Input Voltage, Power, and Current.....	43
11.2	Current Interrupt Protection and Power, Voltage, and Current Monitoring	43
11.3	Filtering and Capacitance.....	44
11.4	Grounding and Return.....	44
12	Physical Specifications.....	44
13	Environmental.....	45
14	Electromagnetic Interference Mitigation	46

Table of Figures

Figure 1. Top Level Block Diagram	2
Figure 2. Management Block Diagram.....	7
Figure 3. UART Block Diagram	9
Figure 4. I2C Block Diagram	10
Figure 5. DDR4 SPD I2C Block Diagram	11
Figure 6. JTAG Block Diagram	13
Figure 7. Rack Interface Block Diagram	16
Figure 8. PROCHOT Block Diagram	19
Figure 9. PWRBRK# Block Diagram	19
Figure 10. MEM VRHOT Block Diagram	20
Figure 11. MEM EVENT_L Block Diagram	20
Figure 12. Motherboard Layout.....	21
Figure 13. SATA Power Connector Pin Numbering.....	34
Figure 14. SATA Power Expansion Connector Pin Numbering.....	34
Figure 15. Mini-Fit Connector Pin Numbering.....	36
Figure 16. Server Management Connector Pin Numbering.....	36
Figure 17. OCuLink x8 Pin Numbering	39
Figure 18. NCSI Connector Pin Numbering	40
Figure 19. Internal USB Connector Pinout	40
Figure 20. Fan Control Connector Pin Numbering.....	42
Figure 21. TPM Connector	42
Figure 22. Example Motherboard Drawing.....	45

Table of Tables

Table 1. List of Specifications	1
Table 2. CPU PCIe Port Mapping	5
Table 3. Jumpers	13
Table 4. LEDs	14
Table 5. Server Power Status LED Description	14
Table 6. Attention LED Description	15
Table 7. Slot ID Decode	16
Table 8. PCIe x8 connector pinout	23
Table 9. PCIe x16 connector pinout	25
Table 10. PCIe x32 Connector Pinout - 200 Pin	27
Table 11. PCIe x32 Connector Pinout - 60 Pin	30
Table 12. PCIe Cable Connector Pinout	31
Table 13. M.2 connector pinout	32
Table 14. SATA Power Connector	33
Table 15. SATA Power Expansion Connector Pinout	34
Table 16. 12V Power Connector	35
Table 17. 1U Management Connector	36
Table 18. Management Expansion Connector	37
Table 19. OCuLink x8 Connector	38
Table 20. NCSI Connector	39
Table 21. Internal USB Connector	40
Table 22. Fan Control Connector	41
Table 23. TPM Connector Pinout	42
Table 24. Input Power Requirements	43
Table 25. Environmental Requirement	45

1 Project Olympus Specifications List

Table 1 lists the Project Olympus system specifications.

Table 1. List of Specifications

Specification title	Description
Project Olympus Server Rack Specification	Describes the mechanical rack hardware used in the system
Project Olympus Server Mechanical Specification	Describes the mechanical structure for the server used in the system.
Project Olympus Universal Motherboard Specification	Describes the server motherboard general requirements.
Project Olympus PSU Specification	Describes the Power Supply Unit (PSU) used in the server
Project Olympus Power Management Distribution Unit Specification	Describes the Power Management Distribution Unit (PMDU).
Project Olympus Rack Manager Specification	Describes the Rack Manager PCBA used in the PMDU.

This document is intended for designers and engineers who will be building servers for Project Olympus systems.

2 Overview

This specification describes the Project Olympus AMD Server Motherboard. This is an implementation specific specification under the Project Olympus Universal Motherboard Specification.

Refer to respective specifications for other elements of the Project Olympus system such as Power Supply Unit (PSU), Rack Manager (RM), Power and Management Distribution Unit (PMDU), and Server Rack.

This specification covers block diagram, management sub-system, power management, FPGA Card support, IO connectors, and physical specifications of the Server Motherboard.

3 Background

The server motherboard is the computational element of the server. The motherboard includes a full server management solution and supports interfaces to integrated or rear-access 12V Power Supply Units (PSUs).

The Server optionally interfaces to a rack-level Power and Management Distribution Unit (PMDU).

The PMDU provides power to the Server and interfaces to the Rack Manager (RM).

The motherboard design provides optimum front-cable access (cold aisle) for external IO such as networking and storage as well as standard PCIe cards. This enables flexibility to support many configurations.

4 Block Diagram

Figure 1 shows the baseline block diagram describing general requirements for the server motherboard.

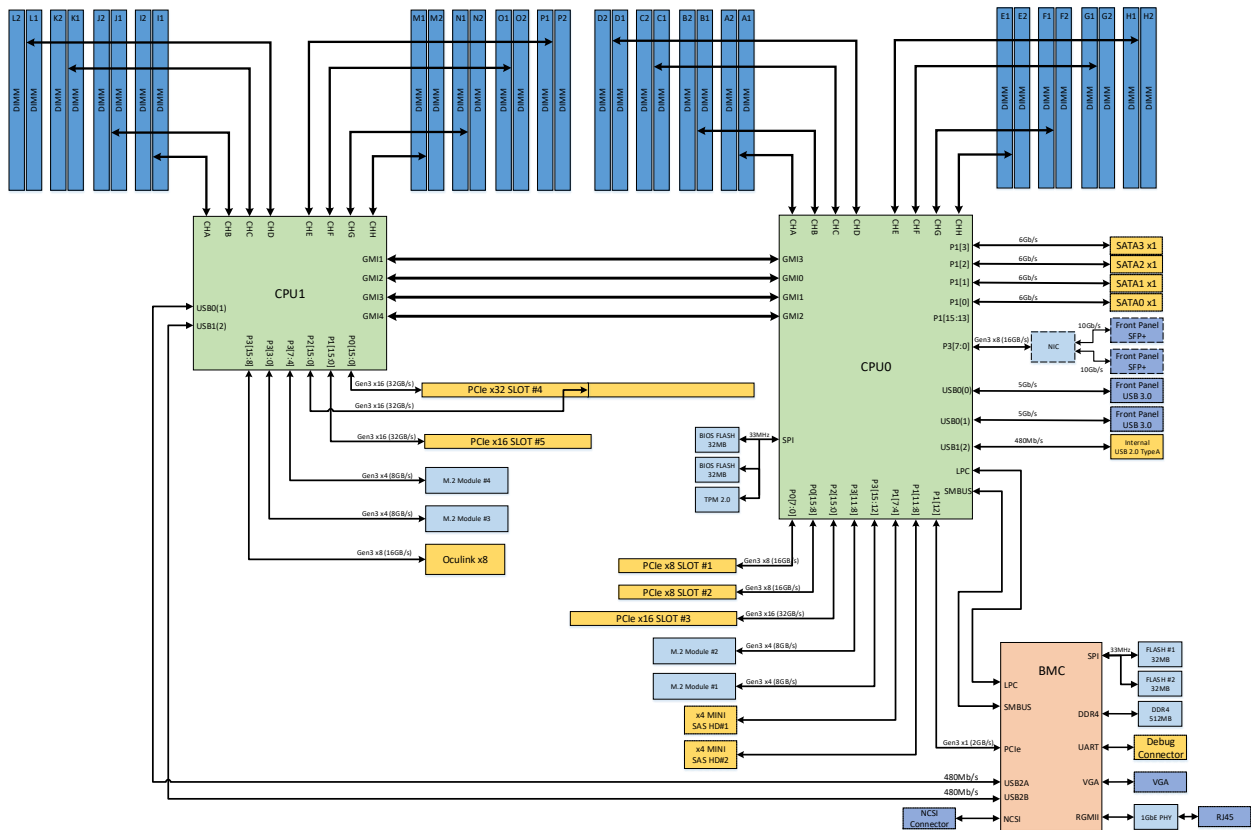


Figure 1. Top Level Block Diagram

5 Features

The motherboard includes support for the following features:

Processor	
Platform	AMD EPYC™ platform
CPU	AMD EPYC™ processors
Sockets	Dual socket operation
TDP Wattage	Up to 180W (Support for all server class SKUs)
Memory	
DIMM Slots	32 total DIMM slots 16 DIMMs per CPU 2 DIMMs per channel
DIMM Type	Double data rate fourth generation (DDR4) Registered DIMM (RDIMM) with Error-Correcting Code (ECC)
DIMM Speed	DDR4-2400 (2DPC), DDR4-2666 (1DPC)
DIMM Size	16GB, 32GB, 64GB
Capacities Supported	128GB, 256GB, 512GB, 756GB, 1TB, 2TB (TBD)
Storage	
SATA	4 local ports @ 6.0 Gb/s (SATA x1) 4 expansion ports @ 6.0Gb/s (MiniSAS HD)
Server Management	
Chipset	BMC Aspeed AST2520/AST2500
Interface	Representational State Transfer (REST) API Windows Management Instrumentation (WMI) Open Management Interface (OMI) Command-Line Interface (CLI)
System Firmware	



BIOS	Unified Extensible Firmware Interface (UEFI), AMI
BMC	AMI
Security	Trusted Platform Module (TPM 2.0) Secure Boot
PCI-Express Expansion	
2 PCIe x8 Slots	Supports PCIe M.2 Riser Cards
2 PCIe x16 Slots	Supports standard PCIe x16 cards
1 PCIe x32 Slot	Supports standard PCIe x16 or custom PCIe x32 cards
4 M.2 Slots	Supports 60mm, 80mm, and 110mm M.2 Cards
1 PCIe x8 Expansion	1 OcuLink x8
2 PCIe x4 Expansion	2 MiniSAS HD PCIe x4
Networking	
LOM	2x 10GbE from CPU0 through NIC on SFP+ Connector
MGMT	1x 1GbE from BMC to RJ45 Connector

5.1 CPUs

The server supports two AMD EPYC™ CPUs for all server class SKUs. The maximum TDP to be supported is 180W.

5.2 DIMMs

The motherboard supports 32 DDR4 RDIMMs with 16 RDIMMs per CPU socket. It supports all available configurations for single, dual, and quad rank RDIMMs per AMD guidelines. The DIMM sockets are also able to support NVDIMM as described in this document. The DIMM pitch is 296.85mils.

The motherboard is designed to support the following technologies but use of these technologies is not validated.

- LRDIMM
- 3DS RDIMM
- DDR4 NVDIMM with 12V power through the DIMM connector

5.3 PCIe Support

5.3.1 CPU PCIe Mapping

Table 5 describes the PCIe port mapping between the CPUs and the PCIe endpoints.

Table 2. CPU PCIe Port Mapping

CPU	PCIe Bus	Destination
0	P0(15:8)	PCIe Slot #2
0	P0(7:0)	PCIe Slot #1
0	P1(15:13)	Reserved
0	P1(12)	BMC
0	P1(11:8)	MiniSAS HD #2
0	P1(7:4)	MiniSAS HD #1 or SATA[7:4]
0	P1(3:0)	SATA[3:0]
0	P2(15:0)	PCIe Slot #3
0	P3(15:12)	M.2 Module #1
0	P3(11:8)	M.2 Module #2
0	P3(7:0)	NIC
1	P0(15:0)	PCIe Slot #4
1	P1(15:0)	PCIe Slot #5
1	P2(15:0)	PCIe Slot #4
1	P3(15:8)	OCuLink x8
1	P3(7:4)	M.2 Module #4
1	P3(3:0)	M.2 Module #3

5.3.2 PCIe x8 Slots

The motherboard supports two PCIe x8 slots to slots 1 and 2 as shown in Figure 2. Each slot supports 1x8 and 2x4 bifurcation. 2x4 bifurcation is supported at the connector with the addition of a 2nd PCIe clock to the standard PCIe pinout. The primary purpose of the slots is to support M.2 Modules with each slot capable of supporting two modules. Use of the modules requires a PCIe riser edge card to connect the modules to the PCIe bus. The riser is capable of supporting 60mm, 80mm, and 110mm M.2 Modules.

5.3.3 PCIe x16/32 Slots

The motherboard supports two PCIe x16 slots and one PCIe x32 (2x16) slot as shown in Figure 2. Each slot supports a standard PCIe form factor card using a riser card to interface to the PCIe connector. The size of the card supported is dependent on the height of the tray assembly. 1U trays can support FHHL PCIe cards. 2U trays can support FHFL cards. Note that Slot #4 is targeted for use by FPGA cards requiring two PCIe x8 channels and this is the default configuration. In this case, additional PCIe can be cabled from the OcuLink x8 connector.



All slots support bifurcation below 1x16 but utilize the standard PCIe connector pinout and do not contain additional clocks. Additional clocks required for bifurcation below 1x16 must be handled with buffer circuitry on the PCIe card.

5.3.4 PCIe Cables

The motherboard supports a single OcuLink x8 connector for the primary purpose of expanding PCIe support to Slot#4 to 24 lanes. PCIe clock and control signals are not supported by the implementation. Physical cabling must avoid any FHHL PCIe card located in Slot #5.

5.3.5 M.2 Modules

The motherboard supports M.2 modules through any of the following methods:

- Standard M.2 connector mounted directly on the motherboard. The motherboard supports up to four on-board M.2 modules.
- M2 Riser Cards in Slots #1 and #2: PCIe Riser card supporting up to two M.2. modules in each slot. All four modules are connected to a PCIe endpoint on CPU0.
- Quad M.2 Carrier Card (OCP AVA): FHHL PCIe Card in standard PCIe format supporting up to four M.2 modules.

For both motherboard and PCIe Card applications, the supported M.2 modules are 60mm, 80mm, and 110mm dual sided form factors (Type 2260, 2280, and 22110).

5.4 PCIe/SATA Expansion

The motherboard supports two MiniSAS-HD x4 connectors, one for PCIe expansion, one for optional PCIe or SATA expansion from the high-speed IO ports on the CPU0. PCIe expansion only miniSAS-HD connector is connected to CPU0 PCIe P1[11:8] and PCIe/SATA expansion miniSAS-HD connector is connected to CPU0 PCIe P1[7:4]. The functionality of the ports (PCIe vs SATA) are controlled by a GPIO output of the BMC.

5.5 SATA Storage

The motherboard supports cabling for up to 8 SATA storage drives. This is accomplished with four x1 SATA connectors connected to SATA ports on the CPU0 P1[3:0] and one MiniSAS-HD x4 connector connected to CPU0 P1 ports P1[7:4] described in section 5.4.

5.6 TPM Module

The motherboard includes a connector to support a TPM 2.0 module connected to the CPU0 SPI bus.

6 Management Subsystem

The Baseboard Management Controller (BMC) circuitry for the motherboard uses the ASPEED AST2500 processor or equivalent. This section describes the requirements for management of the motherboard. Primary features include.

- BMC (ASPEED AST2520/AST2500)
- BMC dedicated 1GbE LAN for server management
- Low pin count (LPC) connection to the chipset to support in-band management
- Advanced Platform Management Link (APML) for CPU out of band environmental control
- FRUID EEPROM for storage of manufacturing data and event
- DIMM temperature monitoring through I2C
- Thermal sensors for inlet and exhaust temperature monitoring
- Power monitoring through the 12V Hot Swap Controller circuitry
- Service LEDs

Figure 2 shows the management block diagram.

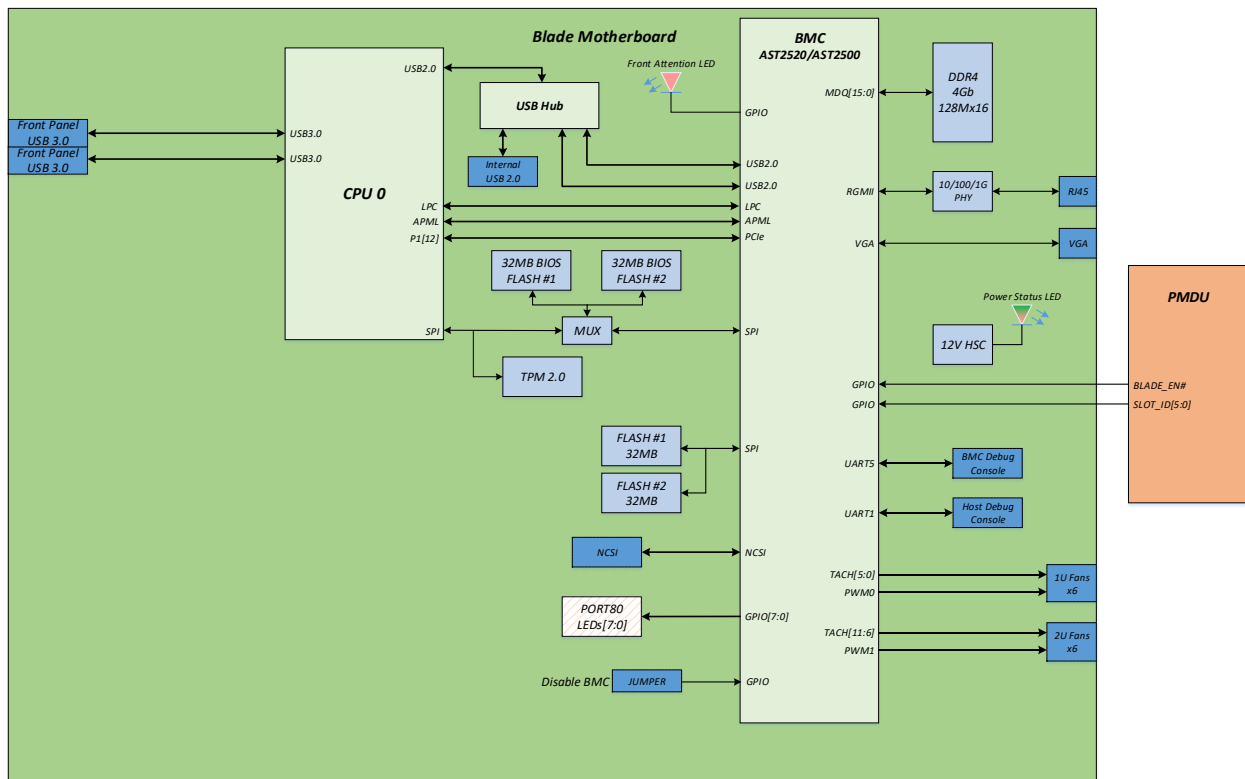


Figure 2. Management Block Diagram

6.1 BMC

The design for the BMC is based on the Aspeed 2500 family and supports either the AST2520 or the AST2500. Primary features of interest include:

- Embedded ARM Processor
- Embedded 16KB/16KB Cache
- DDR4 Memory 512MB (supports up to 1GB)
- 8-bit ECC with error counter
- Redundant NOR/NAND/SPI flash memory
- 14 I2C/SMBus
- 5 UART Controllers
- LPC Bus Interface
- 228 GPIO pins
- VGA port (AST2500 only)
- A single lane of PCIe (AST2500 only)

6.2 BMC DRAM

The BMC requires 512MB of DDR4 memory.

6.3 BMC Boot Flash

The BMC boots from a flash memory device located on the SPI bus. The device size is 256Mb (32MB) minimum and can be used to store FPGA and CPLD recovery images. The device is Winbond W25Q256 or equivalent. A secondary device is supported to provide BMC recovery.

6.4 BIOS Flash

The BIOS utilizes a 256Mb (32MB) Flash BIOS devices available to the CPU and BMC on the SPI. The device is Winbond MPN W25Q256 or equivalent. The BIOS is recoverable from the BMC in the event the chipset is inaccessible.

6.5 1GbE PHY

The server is managed through a 1GbE PHY connected to the BMC. A RJ45 connector located at the front of the motherboard provides 1GbE connectivity to an external management switch. The PHY device is Realtek RTL8211E.

6.6 UARTs

The motherboard supports 2 debug UARTS connected to the BMC as follows:

- UART5 BMC Debug Console
- UART1 Host Debug Console

Figure 3 shows a block diagram of the UART support.

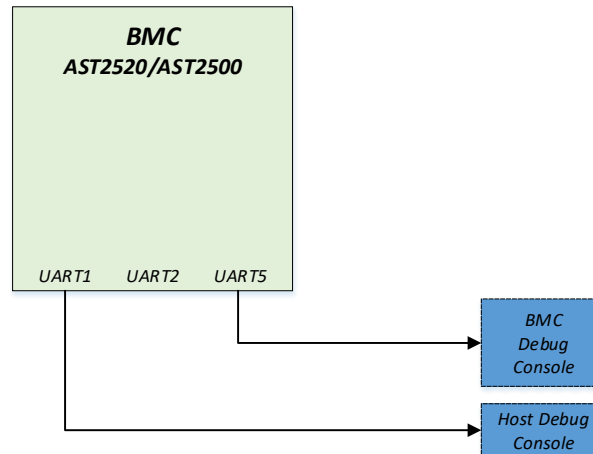


Figure 3. UART Block Diagram

6.7 VGA

The motherboard includes optional support for VGA assuming the AST2500 processor. To support VGA, PCIe is provided from the P1[12] PCIe port of CPU0.

6.8 I2C

The motherboard supports I2C devices available to the BMC. A block diagram of the I2C tree is shown in Figure 4. A brief description of the entities is included below. Note that addresses shown are 8-bit address with the R/W bit as the LSB set to 0 (0xA8=1010100x).

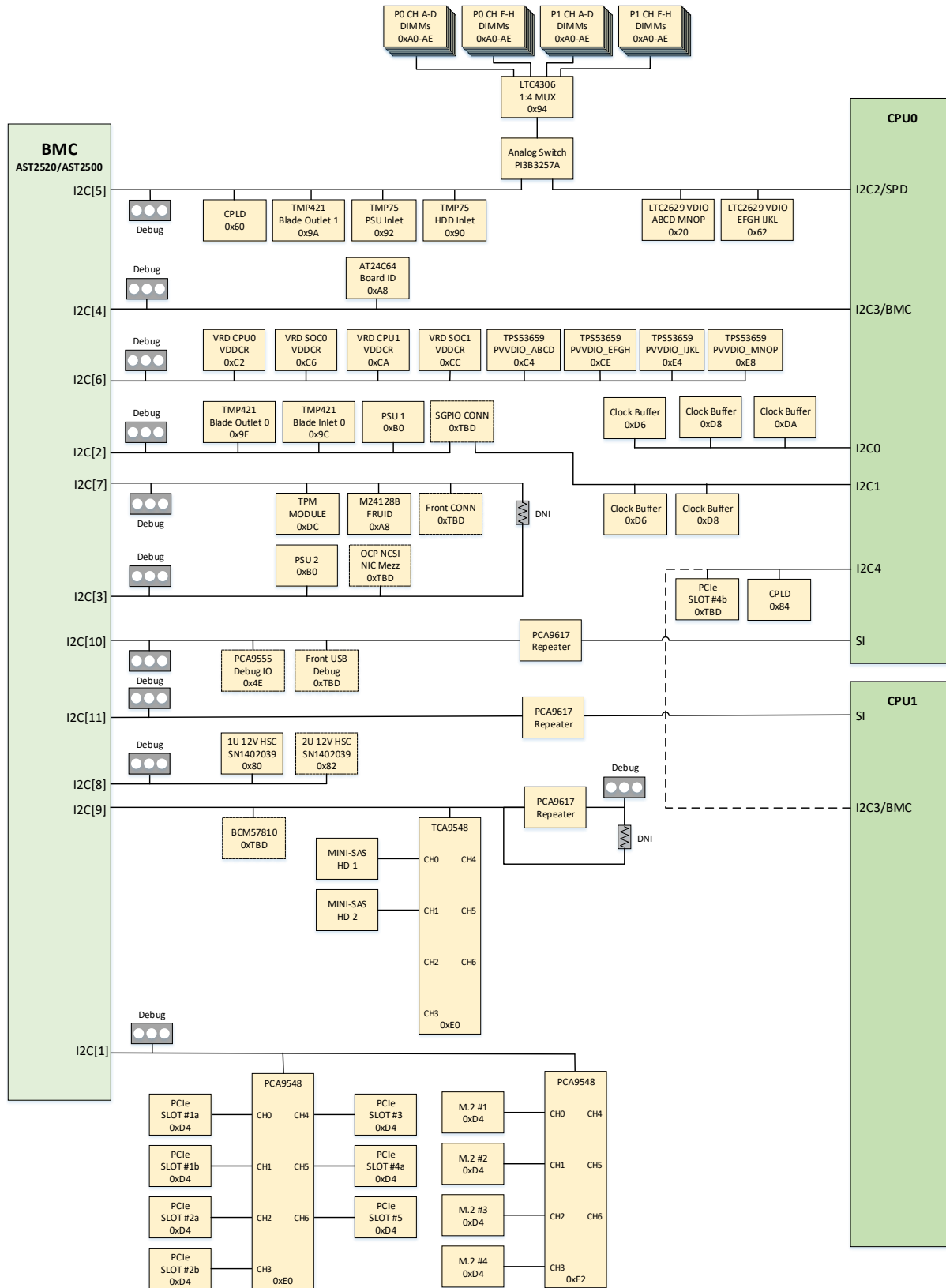


Figure 4. I2C Block Diagram

6.8.1 FRUID PROM

The motherboard includes a 64Kb serial EEPROM MPN AT24C64 or equivalent for the purpose of storing manufacturing data. The device should be available to the BMC on port 7.

6.8.2 Temperature Sensors

The motherboard includes I2C support for two temperature sensors, MPN TMP421 or equivalent, for monitoring the inlet and outlet air temperatures of the motherboard. The motherboard includes provisions to support temperature monitoring of all DIMMs (SPD) and all PCIe slots including M.2 Modules.

Figure 5 below details the SPD I2C bus for the DDR4 Memory. The SPD bus is set to CPU access by default. During boot and reset, CPU controls the SPD bus and beyond those events BMC can control the SPD bus. BMC coordinates and switches the analog switch as needed.

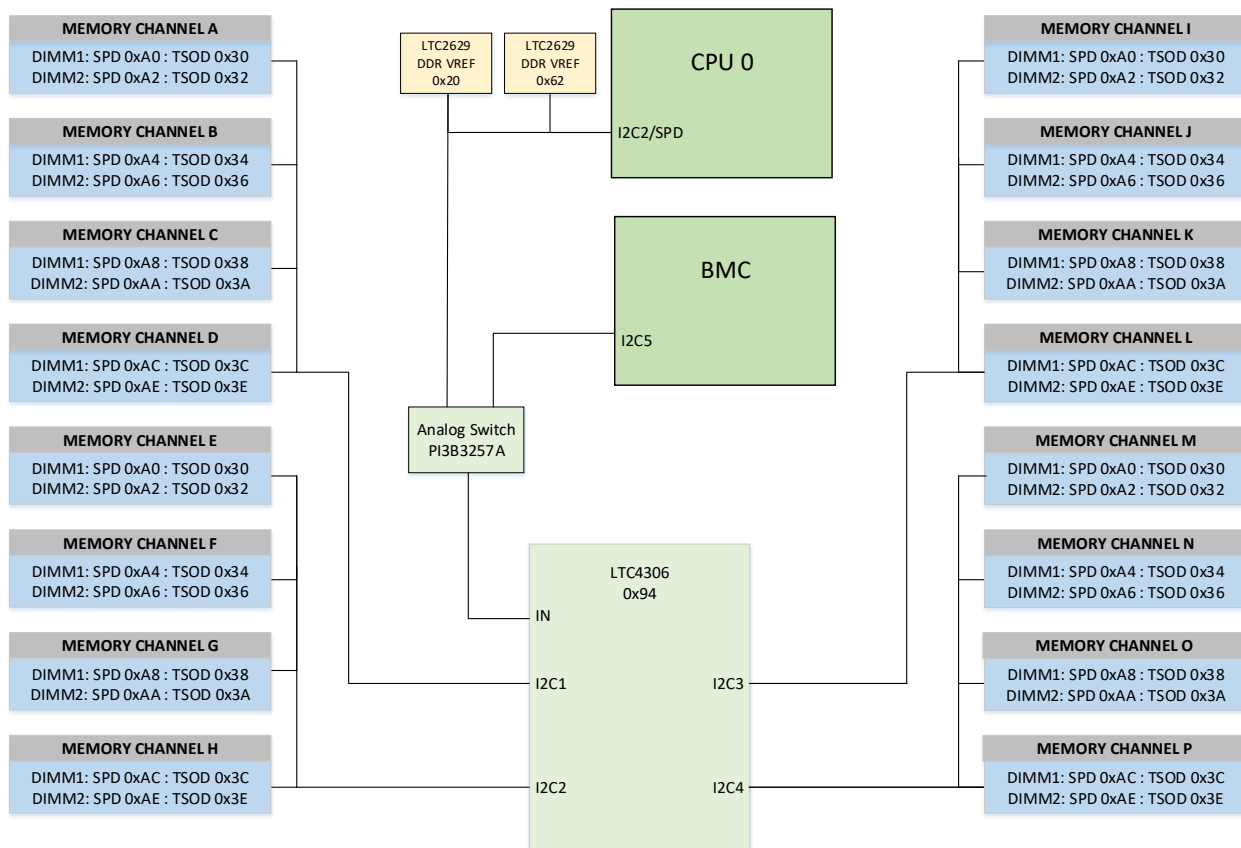


Figure 5. DDR4 SPD I2C Block Diagram

6.8.3 PCIe Devices

The motherboard includes I2C support for all PCIe devices including PCIe Slots and M.2 Modules. Communication is managed through TCA9548 (or equivalent) I2C switches to ensure that devices with the same I2C address are supported from a single I2C port on the BMC.

6.8.4 Voltage Regulators

The motherboard includes I2C support for all the CPU and Memory Subsystem voltage regulators enabling the BMC to monitor health of the individual power rails.

6.8.5 Hot Swap Controllers

The motherboard includes I2C support for up to two SN1402039 hot swap controllers for power monitoring and power capping. Power is monitored by the BMC as part of the power capping function. Accuracy of the SN1402039 is +/-0.7%.

6.8.6 Clock Buffers

There are five PCIe clock buffers on the motherboard. These clock buffers fan out the PCIe clocks for the PCIe devices listed in section 5.3.1. These clock buffers are controlled through CPU0 I2C port0 and port1. Figure 7 above shows generic clock devices.

6.9 JTAG

The motherboard supports muxing of the JTAG master on the BMC to support multiple uses as follows.

- Programming of the primary CPLD
- Programming of PCIe Cards (FPGA) located in Slot #4
- Exposure of HDT capabilities to the BMC

A block diagram of logical concept is shown in Figure 8.

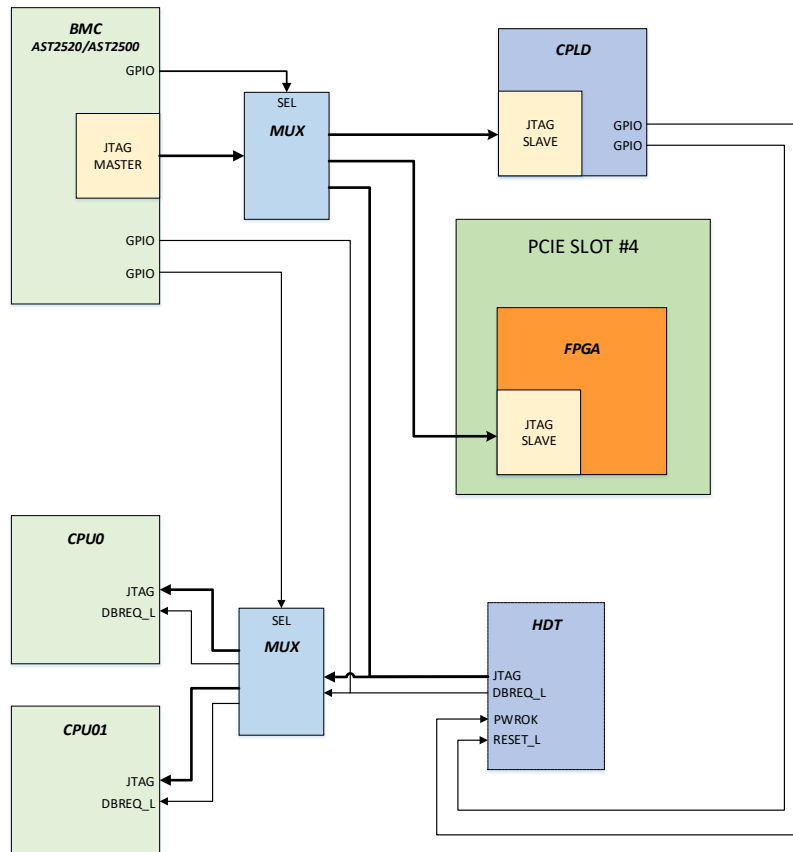


Figure 6. JTAG Block Diagram

6.10 Jumpers

The design supports the jumpers listed in Table 6.

Table 3. Jumpers

Jumper Name	REF Des	Status	Function
BMC Disable (default)	JP18	1-2 Normal (default) 2-3 Hold BMC in Reset	Disables BMC (sets all pins to High impedance)
BIOS USB Recovery	JP12	1-2 BIOS USB flash recovery mode 2-3 Normal (default)	Enables BIOS recovery via USB image update
Clear CMOS	JP3	1-2 Normal (default) 2-3 Clear RTC registers	Clears CMOS
Password Clear	JP11	1-2 Normal (default) 2-3 Password clear	Clears the password

6.11 LEDs

The following sections describe the light-emitting diodes (LEDs) used as indicators on the motherboard. Table 4 lists the minimum LEDs required and provides a brief description. Greater detail for some LEDs is

included in subsequent sections below. The visible diameter, color (λ) and brightness requirements of the LEDs are TBD. All LEDs are visible at the front of the motherboard (cold aisle).

Table 4. LEDs

LED Name	Color	Description
UID LED	Blue	Unit Identification LED
Attention LED	Red	Indicates that Server requires servicing
Power Status LED	Amber/Green	Indicates Power Status of the motherboard
SATA HDD Activity	Green	Indicates R/W activity to HDDs
Post Code	Green	Indicates the Boot status of the motherboard (Port 80)
GbE Port 0 Activity	Green	Indicates activity on 10GbE Port 0 (not supported for production)
GbE Port 0 Speed	Green/Orange	Green=high speed, Orange=Low speed (not supported for production)
PSU1 Status LED	Green/Amber	Status LED for PSU1 <ul style="list-style-type: none"> • Solid Green = AC and DC Power Good • Blinking Green = Battery Power Good • Solid Amber = Failure of PSU Phase • Blinking Amber = Failure of 2 PSU Phases
PSU2 Status LED	Green/Amber	Status LED for PSU2 (Optional) <ul style="list-style-type: none"> • Solid Green = AC and DC Power Good • Blinking Green = Battery Power Good • Solid Amber = Failure of PSU Phase • Blinking Amber = Failure of 2 PSU Phases
P5V Stby LED	Green	Indicates 5V Standby power is present
P12V Aux LED	Green	Indicates 12V Auxiliary power is present
Bootup LED	Green	Indicates system firmware boot up
BMC Heartbeat	Green	Blinks to indicate BMC is alive
Alert LED	Red	Indicates errors occur on the motherboard

6.11.1 UID LED

The motherboard supports a blue UID (unit ID) LED used to help visually locate a specific server within a datacenter.

6.11.2 Power Status LED

When a server is first inserted, the Power Status LED turns amber if 12V is present at the output of the hot swap controller. This assures that the 12V power is connected and present at the motherboard and that the hot swap controller is enabled.

When the server management software turns on the system power (CPU/Memory/PCIe), the Power Status LED turns green. Note that the power status LED may be driven by an analog resistor network tied directly to a power rail and is not an indication of the health of the server. Table 5 describes the operation of the Power Status LED.

Table 5. Server Power Status LED Description

LED status	Condition
Off	12V power is absent or Blade_EN# is de-asserted
Solid Amber ON	Blade_EN# is asserted, 12V power output from the Hot Swap Controller is present.

Solid Green ON	Indicates that the management (BMC) is booted and system power is enabled (CPU/Memory/PCIe).
-----------------------	--

6.11.3 Attention LED

The attention LED directs the service technicians to the server that requires service. When possible, server diagnostics are used to direct repairs. The attention LED is driven by a single BMC GPIO. Table 9 describes the operation of the attention LED.

Table 6. Attention LED Description

LED status	Condition
Off	No attention indicated
Solid RED	System needs attention

6.11.4 PSU Status LEDs

The motherboard supports four PSU status LEDs (2 per PSU). Each PSU is comprised of 2 individual status LEDs indicating the PSU status as shown in Table 4. These LEDs support the WCS P2010 PSU. Standard PSUs may not support external LEDs.

6.12 Fan Control

The motherboard supports control of twelve 40mm fans located at the rear of the server assembly. Fan control is divided between two connectors enabling two separate fan zones. Each connector supports 12V power, a single PWM, and six TACH signals for controlling up to 6 fans in a single zone.

7 Power Management

The motherboard provides a rear connector for interfacing the motherboard to a 12V PSU. The motherboard also provides a separate rear management connector for enabling external control of server power. A block diagram of the interface is shown in Figure 7.

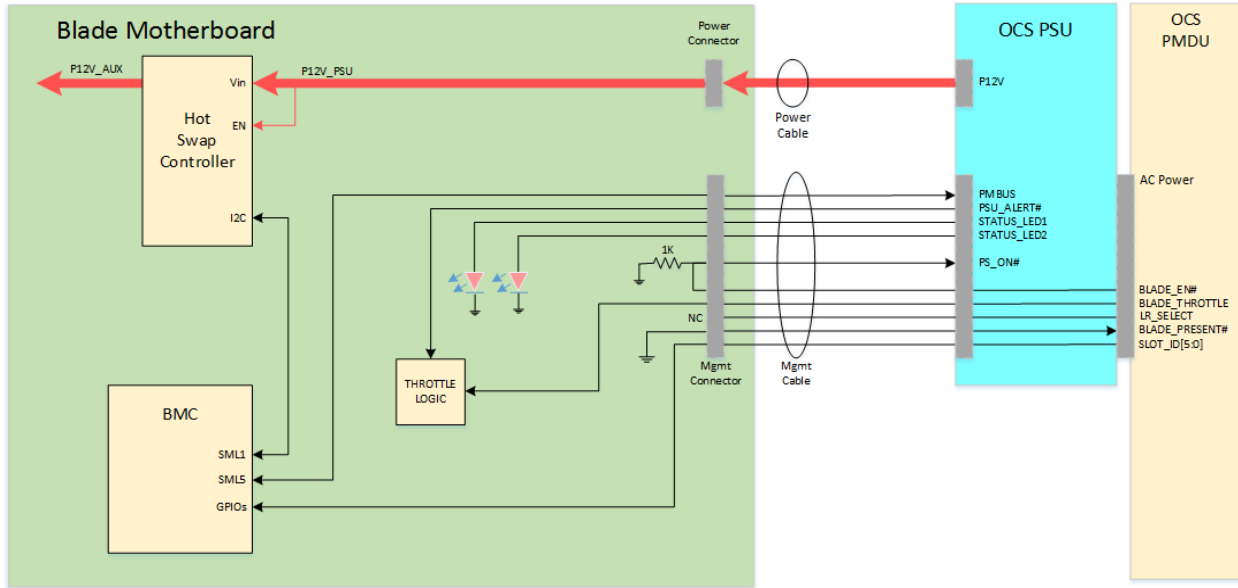


Figure 7. Rack Interface Block Diagram

7.1 Rack Management

The motherboard supports server control through the PMDU. The following describes the management interfaces.

- PWR_EN# - Active low signal used to enable/disable power to the P2010 PSU. A 1K ohm pulldown resistor is used on the motherboard to ensure a default low state (active) if the Rack Manager is not present. This signal connects to the PS_ON# signal of the PSU. When in high state (inactive), this signal disables output power from the P2010 PSU.
- SERVER_PRESENT# - Active low signal used to communicate physical presence of the server to the Rack Manager. This signal should be tied to GND on the motherboard.
- SERVER_THROTTLE - Active high signal used to put the motherboard into a low power (power cap) state. This signal should default low (inactive) if the Rack Manager is not present. This signal is fanned out from the Rack Manager to multiple servers and therefore the circuit design must support electrical isolation of this signal from the motherboard power planes.
- SLOT_ID[5:0] – Identifies the physical rack slot in which the server is installed. ID is hard set by the PMDU. The ID decoding is shown below in Table 7.

LR_SELECT – Spare signal. Used to differentiate between left and right slots for a dual-node implementation.

Table 7. Slot ID Decode

Slot	SLOT_ID[5:0]	Slot	SLOT_ID[5:0]
Slot 1	000000	Slot 25	100000
Slot 2	000001	Slot 26	100001

Slot 3	000010	Slot 27	100010
Slot 4	000011	Slot 28	100011
Slot 5	000100	Slot 29	100100
Slot 6	000101	Slot 30	100101
Slot 7	001000	Slot 31	101000
Slot 8	001001	Slot 32	101001
Slot 9	001010	Slot 33	101010
Slot 10	001011	Slot 34	101011
Slot 11	001100	Slot 35	101100
Slot 12	001101	Slot 36	101101
Slot 13	010000	Slot 37	110000
Slot 14	010001	Slot 38	110001
Slot 15	010010	Slot 39	110010
Slot 16	010011	Slot 40	110011
Slot 17	010100	Slot 41	110100
Slot 18	010101	Slot 42	110101
Slot 19	011000	Slot 43	111000
Slot 20	011001	Slot 44	111001
Slot 21	011010	Slot 45	111010
Slot 22	011011	Slot 46	111011
Slot 23	011100	Slot 47	111100
Slot 24	011101	Slot 48	111101

7.2 PSU Management

The motherboard supports management of the P2010 PSU through a management cable. Below is a description of the signals supported by PMDU.

- PS_ON# - Active low signal used to enable/disable power to the PSU. This signal is driven by the PWR_EN# signal from Rack Manager. A 1K ohm pulldown resistor is used on the motherboard to ensure a default low state if the RM is not present.
- PSU_ALERT# - Active low signal used to alert the motherboard that a fault has occurred in the PSU. Assertion of this signal by the PSU puts the motherboard into a low power (PROCHOT) state. This signal is also connected to the BMC for monitoring PSU status.
- PMBUS – I2C interface to the PSU. This is used by the BMC to read status of the PSU.
- STATUS_LED – Controls LED to provide visual indication of a PSU fault.

7.3 Hot Swap Controller

The motherboard supports a hot swap controller (HSC), MPN SN1402039, for in-rush current protection and power monitoring. The HSC includes support for the PMBUS interface. The hot swap controller disables 12V to the motherboard over PSU overcurrent limit 72A.

7.4 Power Capping

The motherboard supports throttling of the processors using the Fast PROCHOT mechanism based on monitoring of the motherboards input voltage and power. A block diagram detailing these triggers is shown in Figure 8.

The following triggers are monitored by the BMC and can directly generate PROCHOT# events. Each trigger is filtered by the CPLD. The CPLD ensures that any event trigger will generate a minimum 100ms PROCHOT# pulse.

- Undervoltage – A comparator monitors the 12V output of the HSC and asserts if this voltage falls below 11.5V.
- Overcurrent Alert – The HSC monitors the input current and asserts the trigger if the input current exceeds 65A.
- Overcurrent Protect – The HSC monitors the input current and disables power to the motherboard if the current exceeds 72A.
- HSC ALERT #1 and #2 – The HSC provides two programmable alerts. These alerts are spare inputs and will be disabled by default.

Note that the CPU voltage regulators also can generate PROCHOT triggers to the CPUs.

The motherboard enables power capping of the server from different trigger sources. Assertion of either of the following causes the motherboard to assert PROCHOT and the CPLD to initiate power capping of the server.

- RM THROTTLE# - Throttle signal driven by the Rack Manager indicating that the rack has exceeded its power limit.
- PSU ALERT# - Alert signal driven by the PSU. Assertion indicates an over-current event or that the Olympus PSU has transitioned its power source from AC to battery backup.
- FM_THROTTLE# - Test signal that allows BMC to assert power cap

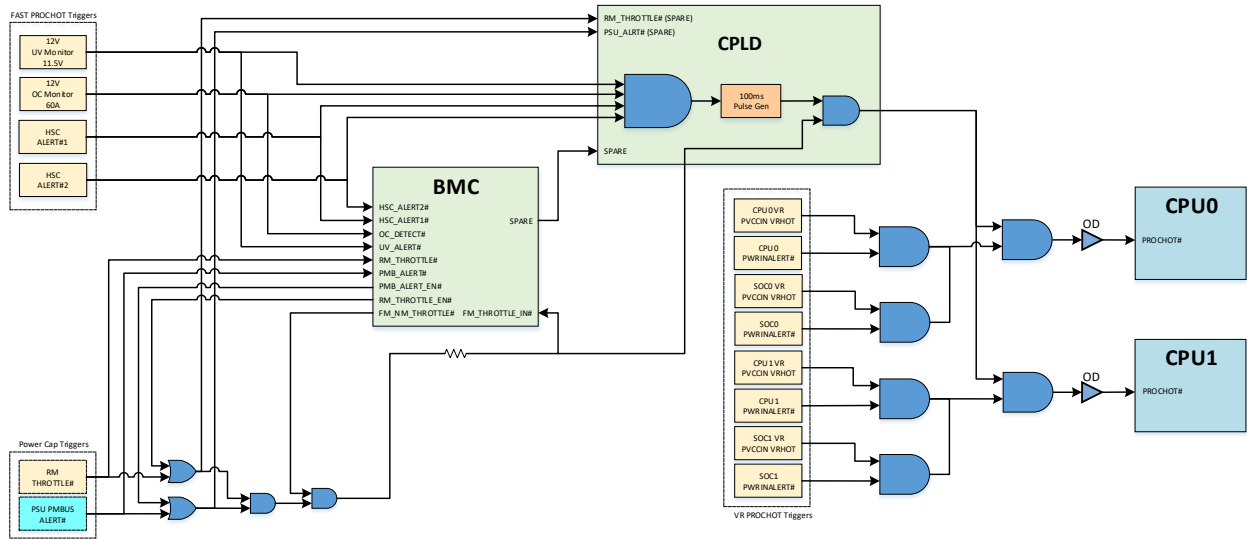


Figure 8. PROCHOT Block Diagram

7.5 PWRBRK#

The motherboard supports Emergency Power Reduction mechanism (PWRBRK#) for the x16 PCIe slots. The primary purpose is to provide a power reduction mechanism for GPGPU cards as part of the throttle and power capping strategy. Figure 9 shows the block diagram for PWRBRK#. PWRBRK# can be triggered by either the RM_THROTTLE# or PSU2_ALERT#. Logic for PWRBRK# is contained in the CPLD. The BMC controls enable/disable monitoring of the two triggers and can also force an event.

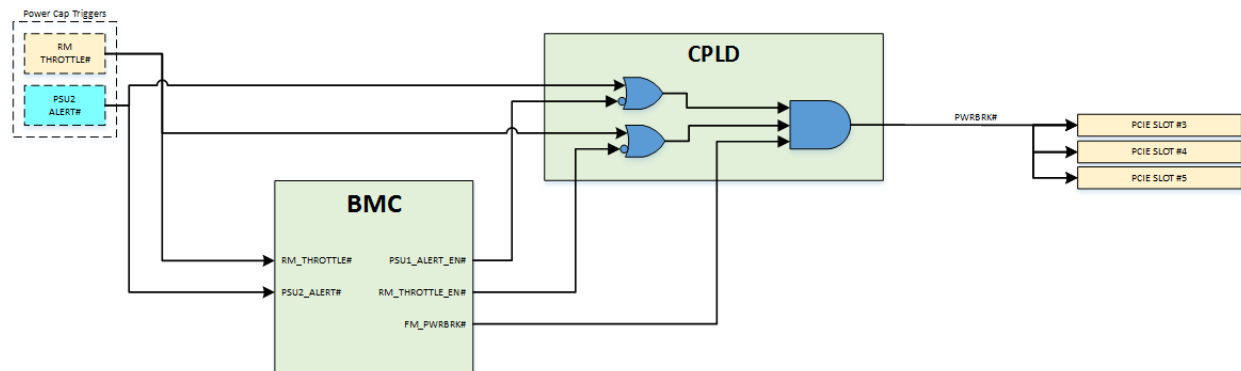


Figure 9. PWRBRK# Block Diagram

7.6 MEM VRHOT and EVENT_L

The motherboard supports memory thermal event mitigation feature. Each channel of CPU memory controller has a dedicated input for DIMM EVENT_L signals. All DIMM EVENT_L signals are connected to CPUs. CPU can be configured to place DIMM into 2x refresh mode or activating throttling. All EVENT_L signals are also routed to CPLD and BMC can either poll the status through I2C bus or CPLD can generate

a trigger through a GPIO to BMC. All MEM VRHOT signals are routed to BMC GPIOs. BMC will log any memory VRHOT and EVENT_L events. A SPARE signal is reserved from BMC to CPLD for MEM VRHOT indication for future implementation. The block diagrams of MEM VRHOT and EVENT_L are shown below.

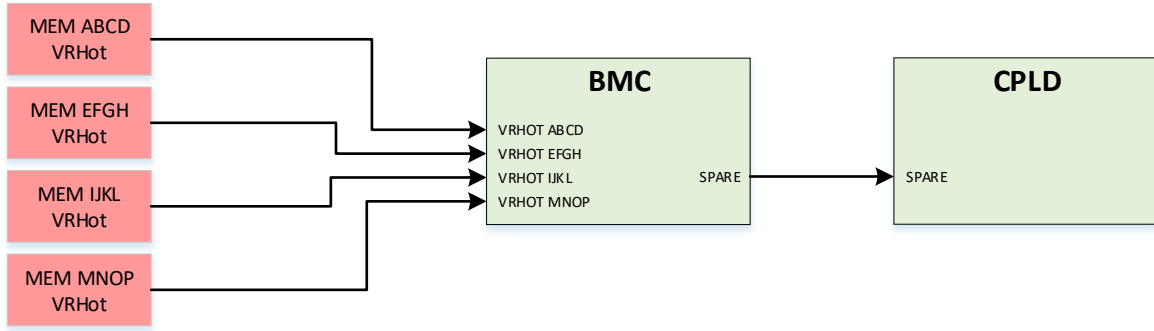


Figure 10. MEM VRHOT Block Diagram

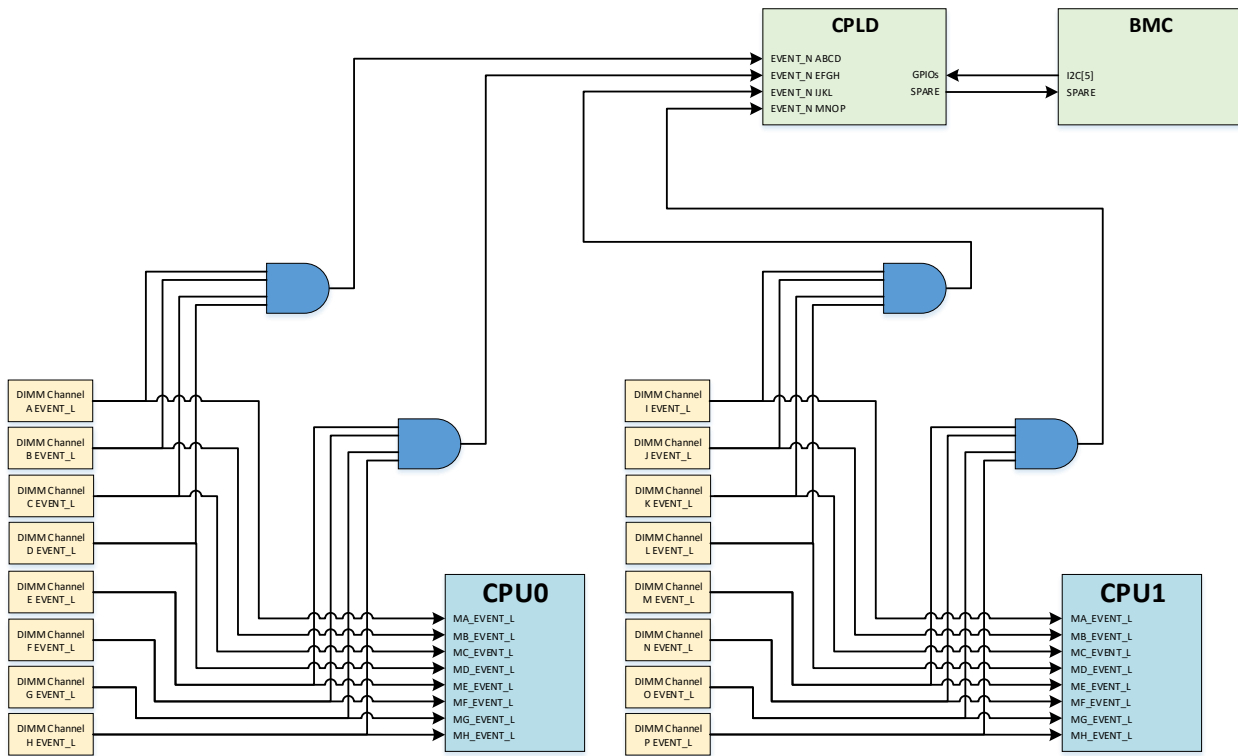


Figure 11. MEM EVENT_L Block Diagram

8 Motherboard Layout

Figure 12 shows a representative layout of the motherboard with approximate locations of major components and connectors.

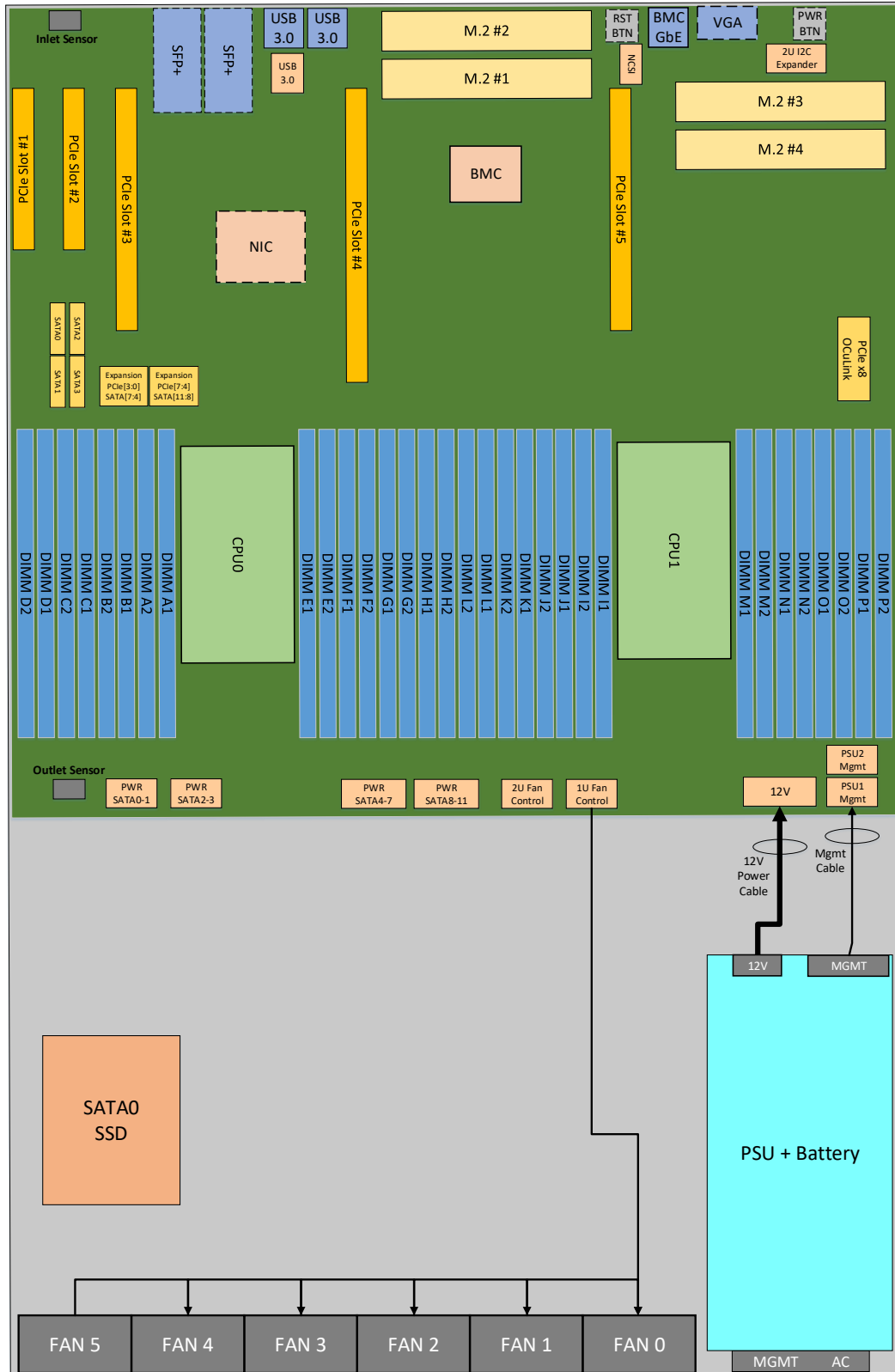


Figure 12. Motherboard Layout

9 Serviceability

9.1 Debug features

The following minimum debug features are supported on the motherboard:

- I2C Debug headers on all I2C ports. Header shall be a 3-pin compatible with standard I2C Protocol Analyzers such as Beagle or Aardvark.
- Debug connectors on all UARTs, 4-pin 2.54mm headers.
- POST LEDs.
- BIOS Debug Support Including:
 - Two socketed BIOS Flash (socket to be removed for production)
 - BIOS recovery jumper connected to CPU GPIO
- HDT Header contains both the JTAG and Debug signals. This connector is for interfacing to HDT tool to control and monitor the processor.
- Two USB 3.0 ports connected to CPU0 USB0 Port 0 and Port 1. The connectors are Type A and the location is at the front of the motherboard for support of servicing at the front of the server assembly. All external USB Ports are capable of operating at USB 3.0, 2.0, or 1.0.
- Two USB 2.0 connections from BMC to CPU.
- BMC disable jumper is attached to GPIO on BMC. The motherboard supports BIOS setting to enable autoboot of motherboard in the event the BMC is disabled.
- CPU Recovery Mode Jumper
- HW jumper to enable BIOS serial debug output

9.2 LED Visibility

Motherboard LEDs determined to be important for communicating status to service personnel are visible at the front (cold aisle) of the motherboard.

- UID LED
- Power Status LED
- Attention LED

10 Motherboard Interfaces

This section describes the connector interfaces to the motherboard.

10.1 PCIe x8 Connectors

The PCIe x8 connector interfaces are designed to support a standard PCIe x8 card as well as the M.2 riser card. The M.2 riser card is a custom edge card PCA that supports two M.2 SSD Modules (NGFF form factor cards) in the SSD Socket 3 format per the PCI Express M.2 Specification. To support two M.2 modules, the PCIe connector interface is altered to support 2 PCIe Gen3 x4 interfaces as well as the SSD specific signals per the PCIE M.2 specification. Table 12 describes the connector pinout. The signals satisfy the electrical requirements of the PCIE Card Electromechanical Specification. The following is a list of pin assignment deviations from that specification needed to support two M.2 modules. These signals are highlighted in red.

- SUSCLK is assigned to pin A6 replacing JTAG TDI pin. Support for SUSCLK is not required.
- LINKWIDTH is assigned to pin B17 replacing PRSNT#2. Enables auto-detection of 2x4 M.2 Interposer or 1x8 standard PCIe card. The design is not required to support PCIe x1 cards.
- REFCLK2+/- is assigned to pins A32/A33 replacing two Reserved pins.
- SMBCLK2 and SMBDAT2 are assigned to pins A7/A8 replacing TDO and TMS pins.

Table 8. PCIe x8 connector pinout

Pin #	Side B Connector		Side A Connector	
	Name	Description	Name	Description
1	+12v	+12 volt power	PRSNT#1	Hot plug presence detect
2	+12v	+12 volt power	+12v	+12 volt power
3	+12v	+12 volt power	+12v	+12 volt power
4	GND	Ground	GND	Ground
5	SMCLK1	SMBus clock	JTAG2	TCK
6	SMDAT1	SMBus data	SUSCLK	Suspend Clk
7	GND	Ground	SMCLK2	SMBus clock
8	+3.3v	+3.3 volt power	SMDAT2	SMBus data
9	JTAG1	+TRST#	+3.3v	+3.3 volt power
10	3.3Vaux	3.3v volt power	+3.3v	+3.3 volt power
11	WAKE#	Link Reactivation	PGOOD	Powergood
Mechanical Key				
12	CLKREQ#	Request Running Clock	GND	Ground
13	GND	Ground	REFCLK1+	Reference Clock Differential pair
14	PETP(0)	Transmitter Lane 0,	REFCLK1-	
15	PETN(0)	Differential pair	GND	Ground
16	GND	Ground	PERP(0)	Receiver Lane 0,
17	LINKWIDTH	0= 2 x4	PERN(0)	Differential pair

		1= 1 x8		
18	GND	Ground	GND	Ground
19	PETP(1)	Transmitter Lane 1,	RSVD	Reserved
20	PETN(1)	Differential pair	GND	Ground
21	GND	Ground	PERP(1)	Receiver Lane 1,
22	GND	Ground	PERN(1)	Differential pair
23	PETP(2)	Transmitter Lane 2,	GND	Ground
24	PETN(2)	Differential pair	GND	Ground
25	GND	Ground	PERP(2)	Receiver Lane 2,
26	GND	Ground	PERN(2)	Differential pair
27	PETP(3)	Transmitter Lane 3,	GND	Ground
28	PETN(3)	Differential pair	GND	Ground
29	GND	Ground	PERP(3)	Receiver Lane 3,
30	RSVD	Reserved	PERN(3)	Differential pair
31	PRSNT#2	Presence Detect	GND	Ground
32	GND	Ground	REFCLK2+	Reference Clock
33	PETP(4)	Transmitter Lane 4,	REFCLK2-	Differential pair
34	PETN(4)	Differential pair	GND	Ground
35	GND	Ground	PERP(4)	Receiver Lane 4,
36	GND	Ground	PERN(4)	Differential pair
37	PETP(5)	Transmitter Lane 5,	GND	Ground
38	PETN(5)	Differential pair	GND	Ground
39	GND	Ground	PERP(5)	Receiver Lane 5,
40	GND	Ground	PERN(5)	Differential pair
41	PETP(6)	Transmitter Lane 6,	GND	Ground
42	PETN(6)	Differential pair	GND	Ground
43	GND	Ground	PERP(6)	Receiver Lane 6,
44	GND	Ground	PERN(6)	Differential pair
45	PETP(7)	Transmitter Lane 7,	GND	Ground
46	PETN(7)	Differential pair	GND	Ground
47	GND	Ground	PERP(7)	Receiver Lane 7,
48	PRSNT#2	Presence detect	PERN(7)	Differential pair
49	GND	Ground	GND	Ground

10.2 PCIe x16 Connectors

The PCIe x16 connector interface is designed to support a standard PCIe x16 full height card. The pinout for supporting PCIe x16 described in Table 13. This interface also supports the PWRBRK# power reduction feature. Note that this signal is declared on pins B12 and B30. This enables support for this feature on existing platforms (B12) and meets the latest PCI SIG definition (B30). For further information, refer to the PCI Express® Card Electromechanical Specification.

Table 9. PCIe x16 connector pinout

Pin	Side B Connector		Side A Connector	
#	Name	Description	Name	Description
1	+12v	+12 volt power	PRSNT#1	Hot plug presence detect
2	+12v	+12 volt power	+12v	+12 volt power
3	+12v	+12 volt power	+12v	+12 volt power
4	GND	Ground	GND	Ground
5	SMCLK	SMBus clock	JTAG2	TCK
6	SMDAT	SMBus data	JTAG3	TDI
7	GND	Ground	JTAG4	TDO
8	+3.3v	+3.3 volt power	JTAG5	TMS
9	JTAG1	+TRST#	+3.3v	+3.3 volt power
10	3.3Vaux	3.3v volt power	+3.3v	+3.3 volt power
11	WAKE#	Link Reactivation	PWRGD	Power Good
Mechanical Key				
12	PWRBRK#	Power Reduction	GND	Ground
13	GND	Ground	REFCLK+	Reference Clock
14	PETP(0)	Transmitter Lane 0,	REFCLK-	Differential pair
15	PETN(0)	Differential pair	GND	Ground
16	GND	Ground	PERP(0)	Receiver Lane 0,
17	PRSNT#2	Presence detect	PERN(0)	Differential pair
18	GND	Ground	GND	Ground
19	PETP(1)	Transmitter Lane 1,	RSVD	Reserved
20	PETN(1)	Differential pair	GND	Ground
21	GND	Ground	PERP(1)	Receiver Lane 1,
22	GND	Ground	PERN(1)	Differential pair
23	PETP(2)	Transmitter Lane 2,	GND	Ground
24	PETN(2)	Differential pair	GND	Ground
25	GND	Ground	PERP(2)	Receiver Lane 2,

26	GND	Ground	PERN(2)	Differential pair
27	PETP(3)	Transmitter Lane 3,	GND	Ground
28	PETN(3)	Differential pair	GND	Ground
29	GND	Ground	PERP(3)	Receiver Lane 3,
30	PWRBRK#	Power Reduction	PERN(3)	Differential pair
31	PRSNT#2	Hot plug detect	GND	Ground
32	GND	Ground	RSVD	Reserved
33	PETP(4)	Transmitter Lane 4,	RSVD	Reserved
34	PETN(4)	Differential pair	GND	Ground
35	GND	Ground	PERP(4)	Receiver Lane 4,
36	GND	Ground	PERN(4)	Differential pair
37	PETP(5)	Transmitter Lane 5,	GND	Ground
38	PETN(5)	Differential pair	GND	Ground
39	GND	Ground	PERP(5)	Receiver Lane 5,
40	GND	Ground	PERN(5)	Differential pair
41	PETP(6)	Transmitter Lane 6,	GND	Ground
42	PETN(6)	Differential pair	GND	Ground
43	GND	Ground	PERP(6)	Receiver Lane 6,
44	GND	Ground	PERN(6)	Differential pair
45	PETP(7)	Transmitter Lane 7,	GND	Ground
46	PETN(7)	Differential pair	GND	Ground
47	GND	Ground	PERP(7)	Receiver Lane 7,
48	PRSNT#2	Hot plug detect	PERN(7)	Differential pair
49	GND	Ground	GND	Ground
50	PETP(8)	Transmitter Lane 8,	RSVD	Reserved
51	PETN(8)	Differential pair	GND	Ground
52	GND	Ground	PERP(8)	Receiver Lane 8,
53	GND	Ground	PERN(8)	Differential pair
54	PETP(9)	Transmitter Lane 9,	GND	Ground
55	PETN(9)	Differential pair	GND	Ground
56	GND	Ground	PERP(9)	Receiver Lane 9,
57	GND	Ground	PERN(9)	Differential pair
58	PETP(10)	Transmitter Lane 10,	GND	Ground
59	PETN(10)	Differential pair	GND	Ground
60	GND	Ground	PERP(10)	Receiver Lane 10,
61	GND	Ground	PERN(10)	Differential pair

62	PETP(11)	Transmitter Lane 11,	GND	Ground
63	PETN(11)	Differential pair	GND	Ground
64	GND	Ground	PERP(11)	Receiver Lane 11,
65	GND	Ground	PERN(11)	Differential pair
66	PETP(12)	Transmitter Lane 12,	GND	Ground
67	PETN(12)	Differential pair	GND	Ground
68	GND	Ground	PERP(12)	Receiver Lane 12,
69	GND	Ground	PERN(12)	Differential pair
70	PETP(13)	Transmitter Lane 13,	GND	Ground
71	PETN(13)	Differential pair	GND	Ground
72	GND	Ground	PERP(13)	Receiver Lane 13,
73	GND	Ground	PERN(13)	Differential pair
74	PETP(14)	Transmitter Lane 14,	GND	Ground
75	PETN(14)	Differential pair	GND	Ground
76	GND	Ground	PERP(14)	Receiver Lane 14,
77	GND	Ground	PERN(14)	Differential pair
78	PETP(15)	Transmitter Lane 15,	GND	Ground
79	PETN(15)	Differential pair	GND	Ground
80	GND	Ground	PERP(15)	Receiver Lane 15,
81	PRSNT#2	Hot plug present detect	PERN(15)	Differential pair
82	RSVD#2	Hot Plug Detect	GND	Ground

10.3 PCIe x32 Connector

The PCIe x32 connector interface is designed to support a standard PCIe x32 full-height card. Use of PCIe x32 is optional for the front I/O slot and is primarily intended as a future growth targeting slot #4. The interface is comprised of two Samtec HSEC8 connectors: 200 pin MPN DFHSK0FS015 and 60 pin MPN DFHS60FS042. The pinouts for the 200 pin and 60 pin connectors are shown in Table 10 and Table 11 respectively. Key features for this interface includes:

- Supports two PCIe x16 interfaces
- Supports auto-bifurcation (Config ID)
- Supports up to 6 PCIe Clocks
- Supports two SMBus interfaces
- Supports JTAG Interface
- Supports USB 2.0 Interface

Table 10. PCIe x32 Connector Pinout - 200 Pin

Pin	Side A Connector		Side B Connector		Pin
#	Name	Description	Name	Description	#
1	P12V	+12 volt power	P12V	+12 volt power	2
3	P12V	+12 volt power	P12V	+12 volt power	4
5	P12V	+12 volt power	P12V	+12 volt power	6
7	P12V	+12 volt power	P12V	+12 volt power	8
9	P12V	+12 volt power	P12V	+12 volt power	10
11	P12V	+12 volt power	P12V	+12 volt power	12
13	GND	Ground	GND	Ground	14
15	BMC_SMBDAT	SMBus to BMC	BMC_ALERT#	SMBus Alert to BMC	16
17	BMC_SMCLK	SMBus to BMC	SLT_CFG1	Slot Configuration Bit1	18
19	SLT_CFG0	Slot Configuration Bit0	PWRBREAK#	Power Break	20
21	P3V3	+3.3 volt power	P3V3	+3.3 volt power	22
23	P3V3	+3.3 volt power	P3V3	+3.3 volt power	24
25	P3V3_STBY	+3.3 volt stby power	GND	Ground	26
27	CPU_ALERT#	SMBus Alert to CPU	WAKE#	Wake	28
29	PERST#	PCIe Reset	CPU_SMDAT	SMBus to CPU	30
31	GND	Ground	CPU_SMCLK	SMBus to CPU	32
33	CLK_100M_DP<0>	Reference Clock	GND	Ground	34
35	CLK_100M_DN<0>	Differential pair	CLK_100M_DP<1>	Reference Clock	36
37	GND	Ground	CLK_100M_DN<1>	Differential pair	38
39	CLK_100M_DP<2>	Reference Clock	GND	Ground	40
41	CLK_100M_DN<2>	Differential pair	CLK_100M_DP<3>	Reference Clock	42
43	GND	Ground	CLK_100M_DN<3>	Differential pair	44
45	CLK_100M_DP<4>	Reference Clock	GND	Ground	46
47	CLK_100M_DN<4>	Differential pair	CLK_100M_DP<5>	Reference Clock	48
49	GND	Ground	CLK_100M_DN<5>	Differential pair	50
51	P3E_P0_TXP<15>	Transmitter Lane 15,	GND	Ground	52
53	P3E_P0_TXN<15>	Differential pair	P3E_P0_RXP<15>	Receiver Lane 15,	54
55	GND	Ground	P3E_P0_RXN<15>	Differential pair	56
57	P3E_P0_TXP<14>	Transmitter Lane 14,	GND	Ground	58
59	P3E_P0_TXN<14>	Differential pair	P3E_P0_RXN<14>	Receiver Lane 14,	60
61	GND	Ground	P3E_P0_RXP<14>	Differential pair	62
63	RSVD1	Reserved	GND	Ground	64
65	GND	Ground	RSVD2	Reserved	66
67	P3E_P0_TXN<13>	Transmitter Lane 13,	GND	Ground	68
69	P3E_P0_TXP<13>	Differential pair	P3E_P0_RXP<13>	Receiver Lane 13,	70
71	GND	Ground	P3E_P0_RXN<13>	Differential pair	72
73	P3E_P0_TXN<12>	Transmitter Lane 12,	GND	Ground	74
75	P3E_P0_TXP<12>	Differential pair	P3E_P0_RXP<12>	Receiver Lane 12,	76
77	GND	Ground	P3E_P0_RXN<12>	Differential pair	78
79	P3E_P0_TXN<11>	Transmitter Lane 11,	GND	Ground	80
81	P3E_P0_TXP<11>	Differential pair	P3E_P0_RXP<11>	Receiver Lane 11,	82
83	GND	Ground	P3E_P0_RXN<11>	Differential pair	84
85	P3E_P0_TXN<10>	Transmitter Lane 10,	GND	Ground	86

Open Compute Project • Project Olympus AMD EPYC™ Processor Motherboard Specification

87	P3E_P0_TXP<10>	Differential pair	P3E_P0_RXP<10>	Receiver Lane 10,	88
89	GND	Ground	P3E_P0_RXN<10>	Differential pair	90
91	P3E_P0_TXP<9>	Transmitter Lane 9,	GND	Ground	92
93	P3E_P0_TXN<9>	Differential pair	P3E_P0_RXP<9>	Receiver Lane 9,	94
95	GND	Ground	P3E_P0_RXN<9>	Differential pair	96
97	P3E_P0_TXP<8>	Transmitter Lane 8,	GND	Ground	98
99	P3E_P0_TXN<8>	Differential pair	P3E_P0_RXP<8>	Receiver Lane 8,	100
101	GND	Ground	P3E_P0_RXN<8>	Differential pair	102
103	P3E_P0_TXP<7>	Transmitter Lane 7,	GND	Ground	104
105	P3E_P0_TXN<7>	Differential pair	P3E_P0_RXP<7>	Receiver Lane 7,	106
107	GND	Ground	P3E_P0_RXN<7>	Differential pair	108
109	P3E_P0_TXP<6>	Transmitter Lane 6,	GND	Ground	110
111	P3E_P0_TXN<6>	Differential pair	P3E_P0_RXP<6>	Receiver Lane 6,	112
113	GND	Ground	P3E_P0_RXN<6>	Differential pair	114
115	P3E_P0_TXP<5>	Transmitter Lane 5,	GND	Ground	116
117	P3E_P0_TXN<5>	Differential pair	P3E_P0_RXP<5>	Receiver Lane 5,	118
119	GND	Ground	P3E_P0_RXN<5>	Differential pair	120
121	P3E_P0_TXP<4>	Transmitter Lane 4,	GND	Ground	122
123	P3E_P0_TXN<4>	Differential pair	P3E_P0_RXP<4>	Receiver Lane 4,	124
125	GND	Ground	P3E_P0_RXN<4>	Differential pair	126
127	P3E_P0_TXP<3>	Transmitter Lane 3,	GND	Ground	128
129	P3E_P0_TXN<3>	Differential pair	P3E_P0_RXP<3>	Receiver Lane 3,	130
131	GND	Ground	P3E_P0_RXN<3>	Differential pair	132
133	P3E_P0_TXP<2>	Transmitter Lane 2,	GND	Ground	134
135	P3E_P0_TXN<2>	Differential pair	P3E_P0_RXP<2>	Receiver Lane 2,	136
137	GND	Ground	P3E_P0_RXN<2>	Differential pair	138
139	P3E_P0_TXP<1>	Transmitter Lane 1,	GND	Ground	140
141	P3E_P0_TXN<1>	Differential pair	P3E_P0_RXP<1>	Receiver Lane 1,	142
143	GND	Ground	P3E_P0_RXN<1>	Differential pair	144
145	P3E_P0_TXP<0>	Transmitter Lane 0,	GND	Ground	146
147	P3E_P0_TXN<0>	Differential pair	P3E_P0_RXP<0>	Receiver Lane 0,	148
149	GND	Ground	P3E_P0_RXN<0>	Differential pair	150
151	P3E_P1_TXP<15>	Transmitter Lane 15,	GND	Ground	152
153	P3E_P1_TXP<15>	Differential pair	P3E_P1_RXP<15>	Receiver Lane 15,	154
155	GND	Ground	P3E_P1_RXN<15>	Differential pair	156
157	P3E_P1_TXP<14>	Transmitter Lane 14,	GND	Ground	158
159	P3E_P1_TXN<14>	Differential pair	P3E_P1_RXP<14>	Receiver Lane 14,	160
161	GND	Ground	P3E_P1_RXN<14>	Differential pair	162
163	P3E_P1_TXP<13>	Transmitter Lane 13,	GND	Ground	164
165	P3E_P1_TXN<13>	Differential pair	P3E_P1_RXP<13>	Receiver Lane 13,	166
167	GND	Ground	P3E_P1_RXN<13>	Differential pair	168
169	P3E_P1_TXP<12>	Transmitter Lane 12,	GND	Ground	170
171	P3E_P1_TXN<12>	Differential pair	P3E_P1_RXP<12>	Receiver Lane 12,	172
173	GND	Ground	P3E_P1_RXN<12>	Differential pair	174
175	P3E_P1_TXP<11>	Transmitter Lane 11,	GND	Ground	176
177	P3E_P1_TXN<11>	Differential pair	P3E_P1_RXP<11>	Receiver Lane 11,	178

179	GND	Ground	P3E_P1_RXN<11>	Differential pair	180
181	P3E_P1_TXP<10>	Transmitter Lane 10,	GND	Ground	182
183	P3E_P1_TXN<10>	Differential pair	P3E_P1_RXP<10>	Receiver Lane 10,	184
185	GND	Ground	P3E_P1_RXN<10>	Differential pair	186
187	P3E_P1_TXP<9>	Transmitter Lane 9,	GND	Ground	188
189	P3E_P1_TXN<9>	Differential pair	P3E_P1_RXP<9>	Receiver Lane 9,	190
191	GND	Ground	P3E_P1_RXN<9>	Differential pair	192
193	P3E_P1_TXP<8>	Transmitter Lane 8,	GND	Ground	194
195	P3E_P1_TXN<8>	Differential pair	P3E_P1_RXP<8>	Receiver Lane 8,	196
197	GND	Ground	P3E_P1_RXN<8>	Differential pair	198
199	PRESENT#	Present signal	GND	Ground	200

Table 11. PCIe x32 Connector Pinout - 60 Pin

Pin #	Side A Golden Finger		Side B Golden Finger		Pin #
	Name	Description	Name	Description	
1	GND	Ground	RSVD2	Reserved	2
3	P3E_P1_TXP<7>	Transmitter Lane 7,	GND	Ground	4
5	P3E_P1_TXN<7>	Differential pair	P3E_P1_RXP<7>	Receiver Lane 7,	6
7	GND	Ground	P3E_P1_RXN<7>	Differential pair	8
9	P3E_P1_TXP<6>	Transmitter Lane 6,	GND	Ground	10
11	P3E_P1_TXN<6>	Differential pair	P3E_P1_RXP<6>	Receiver Lane 6,	12
13	GND	Ground	P3E_P1_RXN<6>	Differential pair	14
15	P3E_P1_TXP<5>	Transmitter Lane 5,	GND	Ground	16
17	P3E_P1_TXN<5>	Differential pair	P3E_P1_RXP<5>	Receiver Lane 5,	18
19	GND	Ground	P3E_P1_RXN<5>	Differential pair	20
21	P3E_P1_TXP<4>	Transmitter Lane 4,	GND	Ground	22
23	P3E_P1_TXN<4>	Differential pair	P3E_P1_RXP<4>	Receiver Lane 4,	24
25	GND	Ground	P3E_P1_RXN<4>	Differential pair	26
27	P3E_P1_TXP<3>	Transmitter Lane 3,	GND	Ground	28
29	P3E_P1_TXN<3>	Differential pair	P3E_P1_RXP<3>	Receiver Lane 3,	30
31	GND	Ground	P3E_P1_RXN<3>	Differential pair	32
33	P3E_P1_TXP<2>	Transmitter Lane 2,	GND	Ground	34
35	P3E_P1_TXN<2>	Differential pair	P3E_P1_RXP<2>	Receiver Lane 2,	36
37	GND	Ground	P3E_P1_RXN<2>	Differential pair	38
39	P3E_P1_TXP<1>	Transmitter Lane 1,	GND	Ground	40
41	P3E_P1_TXN<1>	Differential pair	P3E_P1_RXP<1>	Receiver Lane 1,	42
43	GND	Ground	P3E_P1_RXN<1>	Differential pair	44
45	P3E_P1_TXP<0>	Transmitter Lane 0,	GND	Ground	46
47	P3E_P1_TXN<0>	Differential pair	P3E_P1_RXP<0>	Receiver Lane 0,	48
49	GND	Ground	P3E_P1_RXN<0>	Differential pair	50
51	JTAG_TDI	JTAG TDI	GND	Ground	52
53	JTAG_TDO	JTAG TDO	JTAG_TMS	JTAG TMS	54
55	GND	Ground	JTAG_TCK	JTAG TCK	56
57	USB2_DP	USB 2.0	GND	Ground	58

59	USB2_DN	USB 2.0	JTAG_TRST	JTAG Reset	60
----	---------	---------	-----------	------------	----

10.4 PCIe MiniSAS HD Connectors

The motherboard optionally supports vertical MiniSAS HD connectors for cabling PCIe from the motherboard to rear PCIe expansion cards. The connector supports four lanes of PCIe and the necessary management signals (clocks, PERST#) to operate as a standalone PCIe interface.

Table 12. PCIe Cable Connector Pinout

PCIe Cable Connector Pinout		
Pin	Signal	Description
D9	GND	Ground
D8	TX2-	PCIe Transmit Lane 2
D7	TX2+	PCIe Transmit Lane 2
D6	GND	Ground
D5	TX0-	PCIe Transmit Lane 0
D4	TX0+	PCIe Transmit Lane 0
D3	GND	Ground
D2	SB6	BMC_SMB_CLK
D2	SB5	BMC_SMB_DAT
C1	NC	NC
C2	NC	NC
C3	GND	Ground
C4	TX1+	PCIe Transmit Lane 1
C5	TX1-	PCIe Transmit Lane 1
C6	GND	Ground
C7	TX3+	PCIe Transmit Lane 3
C8	TX3-	PCIe Transmit Lane 3
C9	GND	Ground
B9	GND	Ground
B8	RX2-	PCIe Receive Lane 2
B7	RX2+	PCIe Receive Lane 2
B6	GND	Ground
B5	RX0-	PCIe Receive Lane 0
B4	RX0+	PCIe Receive Lane 0
B3	GND	Ground
B2	GND	GND
B1	PERST#	PERST#
A1	REFCLK+	PCIe Reference Clock
A2	REFCLK-	PCIe Reference Clock
A3	GND	Ground

A4	RX1+	PCIe Receive Lane 1
A5	RX1-	PCIe Receive Lane 1
A6	GND	Ground
A7	RX3+	PCIe Receive Lane 3
A8	RX3-	PCIe Receive Lane 3
A9	GND	Ground

10.5 M.2 Connectors

M.2 connectors are integrated into the motherboard for supporting flash memory expansion. The M.2 connector pinout is shown in Table 13. For more information about the M.2 interface, refer to the PCI Express M.2 Specification.

Table 13. M.2 connector pinout

M.2 Module Standard Pinout					
Pin	Signal	Description	Pin	Signal	Description
74	3.3V	3.3V Power	75	GND	Ground
72	3.3V	3.3V Power	73	GND	Ground
70	3.3V	3.3V Power	71	GND	Ground
68	SUSCLK(32KHz)	Reduce Power Clock	69	NC	Reserved
66	KEY	Module Key	67	GND	Ground
64	KEY	Module Key	65	KEY	Module Key
62	KEY	Module Key	63	KEY	Module Key
60	KEY	Module Key	61	KEY	Module Key
58	NC	Reserved	59	KEY	Module Key
56	NC	Reserved	57	GND	Ground
54	PEWAKE#	PCIe PME Wake (Open Drain)	55	REFLKCP	PCIe Reference Clock
52	CLKREQ#	Reference Clock Request	53	REFLKCN	PCIe Reference Clock
50	PERST#	PCIe Reset	51	GND	Ground
48	NC	Reserved	49	PETP0	PCIe Transmit Lane 0
46	NC	Reserved	47	PETN0	PCIe Transmit Lane 0
44	ALERT#	SMBus ALERT	45	GND	Ground
42	SMB_DATA	SMBus Data	43	PERP0	PCIe Receive Lane 0
40	SMB_CLK	SMBus Clock	41	PERN0	PCIe Receive Lane 0
38	DEVSLEEP	Device Sleep	39	GND	Ground
36	NC	Reserved	37	PETP1	PCIe Transmit Lane 0

34	NC	Reserved	35	PETN1	PCIe Transmit Lane 0
32	NC	Reserved	33	GND	Ground
30	NC	Reserved	31	PERP1	PCIe Receive Lane 0
28	NC	Reserved	29	PERN1	PCIe Receive Lane 0
26	NC	Reserved	27	GND	Ground
24	NC	Reserved	25	PETP2	PCIe Transmit Lane 0
22	NC	Reserved	23	PETN2	PCIe Transmit Lane 0
20	NC	Reserved	21	GND	Ground
18	3.3V	3.3V Power	19	PERP2	PCIe Receive Lane 0
16	3.3V	3.3V Power	17	PERN2	PCIe Receive Lane 0
14	3.3V	3.3V Power	15	GND	Ground
12	3.3V	3.3V Power	13	PETP3	PCIe Transmit Lane 0
10	DAS/DSS#	Drive Active Signal (Open Drain)	11	PETN3	PCIe Transmit Lane 0
8	NC	Reserved	9	GND	Ground
6	NC	Reserved	7	PERP3	PCIe Receive Lane 0
4	3.3V	3.3V Power	5	PERN3	PCIe Receive Lane 0
2	3.3V	3.3V Power	3	GND	Ground
			1	GND	Ground

10.6 SATA Cable Ports

The motherboard supports four x1 SATA standard 7-pin connectors. The motherboard optionally supports up to one x4 MiniSAS HD connectors for expansion cabling of up to 4 additional SATA devices (8 total).

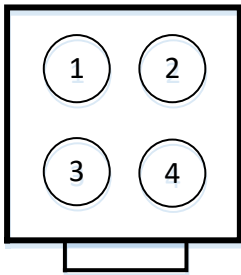
10.7 SATA Power Connector

The motherboard supports two 4-pin Mini-Fit® Jr™ 5566 series power connectors, P/N: Molex 5566-04A or equivalent for supplying power to up to 4 SATA devices. Each connector pin has a maximum 13A current capacity. Table 14 describes the connector pinout. Figure 13 shows a top view of the physical pin numbering.

Table 14. SATA Power Connector

Pin	Signal name	Capacity (in A)
Pin 1 & 2	GND	13A (Black)
Pin 3	12V	9A (Yellow)
Pin 4	5V	9A (Red)

Figure 13. SATA Power Connector Pin Numbering



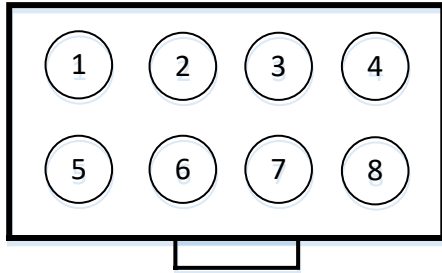
10.8 SATA Power Expansion Connector

The motherboard supports two 8-pin Minit-Fit® Jr™ 5566 series power expansion connectors, Molex P/N 39-28-1083 or equivalent for supplying power to up to 4 additional SATA devices. Each connector has a maximum 13A current capacity. Table 15 describes the connector pinout. Figure 14 shows a top view of the physical pin numbering.

Table 15. SATA Power Expansion Connector Pinout

Pin	Signal name	Capacity (in A)
Pin 1-4	GND	13A (Black)
Pin 5,6	12V	9A (Yellow)
Pin 7,8	5V	9A (Red)

Figure 14. SATA Power Expansion Connector Pin Numbering



10.9 12V Power Connector

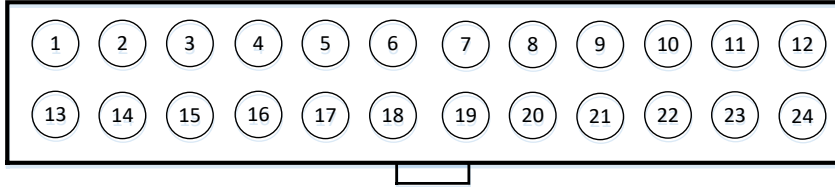
The motherboard supports a 24 pin Mini-Fit Jr or equivalent connector to support 12V cabling from the motherboard to the PSU. The connector supports a maximum of 13A per pin. Table 17 describes the connector pinout. Figure 15 shows a top view of the physical pin numbering. For further information, refer to the Project Olympus PSU Specification.

Table 16. 12V Power Connector

Server Management Connector				
Pin	Signal	I/O	Voltage	Description
1	GND	I	0V	GND from PSU
2	GND	I	0V	GND from PSU
3	GND	I	0V	GND from PSU
4	GND	I	0V	GND from PSU
5	GND	I	0V	GND from PSU
6	GND	I	0V	GND from PSU
7	P12V_PSU	I	12V	12V Power from PSU
8	P12V_PSU	I	12V	12V Power from PSU
9	P12V_PSU	I	12V	12V Power from PSU
10	P12V_PSU	I	12V	12V Power from PSU
11	P12V_PSU	I	12V	12V Power from PSU
12	P12V_PSU	I	12V	12V Power from PSU
13	GND	I	0V	GND from PSU
14	GND	I	0V	GND from PSU
15	GND	I	0V	GND from PSU
16	GND	I	0V	GND from PSU
17	GND	I	0V	GND from PSU
18	GND	I	0V	GND from PSU
19	P12V_PSU	I	12V	12V Power from PSU
20	P12V_PSU	I	12V	12V Power from PSU
21	P12V_PSU	I	12V	12V Power from PSU
22	P12V_PSU	I	12V	12V Power from PSU
23	P12V_PSU	I	12V	12V Power from PSU

24	P12V_PSU	I	12V	12V Power from PSU
----	----------	---	-----	--------------------

Figure 15. Mini-Fit Connector Pin Numbering



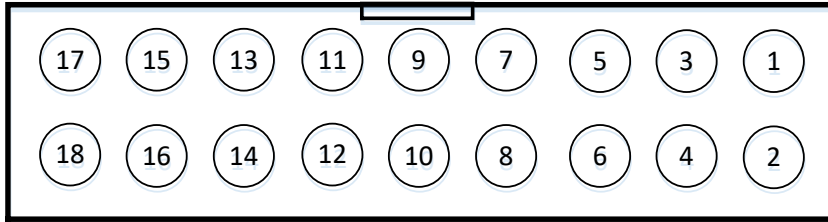
10.10 Management Connector

The motherboard supports a connector for interface management signals from the motherboard to the WCS P2010 PSU. The connector is an 18 pin Molex Picoblade™ series connector, Molex part number 87831-1820 or equivalent. Table 17 describes the connector pinout. Figure 16 shows a top view of the physical pin numbering.

Table 17. 1U Management Connector

Server Management Connector				
Pin	Signal	I/O	Voltage	Description
1	BLADE_EN#	I	3.3V	Enable signal from Rack Manager to HSC on the motherboard
2	LR_SELECT	I	RS232	Left/Right Node Select
3	SLOT_ID0	I	3.3V	SLOT ID from PMDU to motherboard
4	SLOT_ID1	I	3.3V	SLOT ID from PMDU to motherboard
5	RM_THROTTLE#	I	3.3V	Server Throttle control from Rack Manager
6	PRESENT#	O	3.3V	Indicates motherboard presence to the Rack Manager
7	I2C1_SCL	O	3.3V	I2C Clock to PSU1 (PMBus)
8	I2C1_SDA	I/O	3.3V	I2C Data to PSU1 (PMBus)
9	I2C1_GND	I	0V	GND reference for I2Cbus
10	PSU1_PS_ON#	O	3.3V	Turns on PSU1. Pulled low with 1K ohm on MB
11	PSU1_ALERT#	I	3.3V	I2C Alert from the PSU1
12	PSU1_LED0	I	3.3V	PSU1 LED 0(Green)
13	PSU1_LED1	I	3.3V	PSU1 LED 1(Yellow)
14	SLOT_ID2	I	3.3V	SLOT ID from PMDU to motherboard
15	SLOT_ID3	I	3.3V	SLOT ID from PMDU to motherboard
16	SLOT_ID4	I	3.3V	SLOT ID from PMDU to motherboard
17	SLOT_ID5	I	3.3V	SLOT ID from PMDU to motherboard
18	P3V0_BATT	I	3V	3V RTC Battery

Figure 16. Server Management Connector Pin Numbering



10.11 Management Expansion Connector

The motherboard supports an expansion connector for interface management signals from the motherboard to a power adaptor board for power control of expansion devices including second WCS P2010 PSU. The connector is an 18 pin Molex Picoblade™ series connector, Molex part number 87831-1820 or equivalent. This is the same connector as used for the single motherboard Management Connector. Table 18 describes the connector pinout.

Table 18. Management Expansion Connector

Server Management Connector				
Pin	Signal	I/O	Voltage	Description
1	NC	NA	NA	Not Used
2	EXP_SDA	O	3.3V	I2C Data to expansion devices
3	EXP_SCL	I/O	3.3V	I2C Clock to expansion devices
4	GND	I	0V	GND Reference
5	NC	NA	NA	Not Used
6	PSU2_PRESENT#	I	3.3V	
7	I2C2_SCL	O	3.3V	I2C Clock to PSU2 (PMBus)
8	I2C2_SDA	I/O	3.3V	I2C Data to PSU2 (PMBus)
9	I2C2_GND	I	0V	GND reference for I2Cbus
10	PSU2_PS_ON#	O	3.3V	Turns on PSU2. Driven by BMC or CPLD
11	PSU2_ALERT#	I	3.3V	I2C Alert from the PSU2
12	PSU2_LED0	I	3.3V	PSU2 LED 0(Green)
13	PSU2_LED1	I	3.3V	PSU2 LED 1(Yellow)
14	NC			Not Used
15	NC			Not Used
16	NC			Not Used
17	NC			Not Used
18	NC			Not Used

10.12 OCuLink x8 Connector

The motherboard supports a connector for cabling PCIe x8 from the motherboard to the FPGA Card in PCIe Slot #4. The connector for supporting the cable is an 80 pin vertical Molex Nanopitch™ series

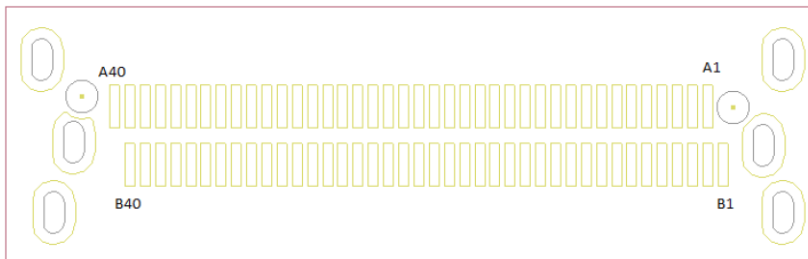
connector, Molex part number 173162-0334 or equivalent. Table 19 describes the connector pinout. Figure 17 shows a top view of the physical pin numbering.

Table 19. OcuLink x8 Connector

Row A			Row B		
Pin	Signal Name	Description	Pin	Signal Name	Description
A1	GND	Ground	B1	GND	Ground
A2	PERp0	PCIe Receive Data to CPU	B2	PETp0	PCIe Transmit Data from CPU
A3	PERn0	PCIe Receive Data to CPU	B3	PETn0	PCIe Transmit Data from CPU
A4	GND	Ground	B4	GND	Ground
A5	PERp1	PCIe Receive Data to CPU	B5	PETp1	PCIe Transmit Data from CPU
A6	PERn1	PCIe Receive Data to CPU	B6	PETn1	PCIe Transmit Data from CPU
A7	GND	Ground	B7	GND	Ground
A8	NC	No Connect	B8	NC	No Connect
A9	NC	No Connect	B9	NC	No Connect
A10	GND	Ground	B10	GND	Ground
A11	NC	No Connect	B11	NC	No Connect
A12	NC	No Connect	B12	CPRSNT#	Cable Present
A13	GND	Ground	B13	GND	Ground
A14	PERp2	PCIe Receive Data to CPU	B14	PETp2	PCIe Transmit Data from CPU
A15	PERn2	PCIe Receive Data to CPU	B15	PETn2	PCIe Transmit Data from CPU
A16	GND	Ground	B16	GND	Ground
A17	PERp3	PCIe Receive Data to CPU	B17	PETp3	PCIe Transmit Data from CPU
A18	PERn3	PCIe Receive Data to CPU	B18	PETn3	PCIe Transmit Data from CPU
A19	GND	Ground	B19	GND	Ground
A20	RSVD	Reserved	B20	RSVD	Reserved
A21	RSVD	Reserved	B21	RSVD	Reserved
A22	GND	Ground	B22	GND	Ground
A23	PERp4	PCIe Receive Data to CPU	B23	PETp4	PCIe Transmit Data from CPU
A24	PERn4	PCIe Receive Data to CPU	B24	PETn4	PCIe Transmit Data from CPU
A25	GND	Ground	B25	GND	Ground
A26	PERp5	PCIe Receive Data to CPU	B26	PETp5	PCIe Transmit Data from CPU

A27	PERn5	PCIe Receive Data to CPU	B27	PETn5	PCIe Transmit Data from CPU
A28	GND	Ground	B28	GND	Ground
A29	NC	No Connect	B29	NC	No Connect
A30	NC	No Connect	B30	NC	No Connect
A31	GND	Ground	B31	GND	Ground
A32	NC	No Connect	B32	NC	No Connect
A33	NC	No Connect	B33	NC	No Connect
A34	GND	Ground	B34	GND	Ground
A35	PERp6	PCIe Receive Data to CPU	B35	PETp6	PCIe Transmit Data from CPU
A36	PERn6	PCIe Receive Data to CPU	B36	PETn6	PCIe Transmit Data from CPU
A37	GND	Ground	B37	GND	Ground
A38	PERp7	PCIe Receive Data to CPU	B38	PETp7	PCIe Transmit Data from CPU
A39	PERn7	PCIe Receive Data to CPU	B39	PETn7	PCIe Transmit Data from CPU
A40	GND	Ground	B40	GND	Ground

Figure 17. Oculink x8 Pin Numbering



10.13 NCSI Connector

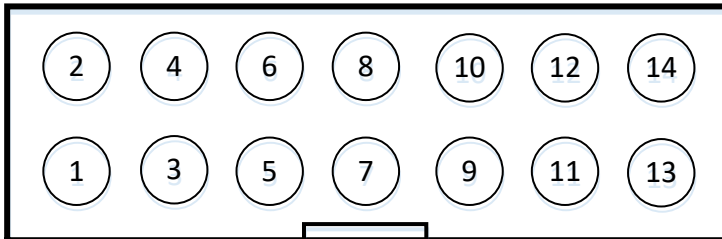
The motherboard supports a connector for cabling NCSI signals from the motherboard to a Network Interface Controller (NIC). The connector for supporting the cable is a 14 pin header connector, Molex part number 52S-H90-14GW50 or equivalent. Table 20 describes the connector pinout. Figure 18 shows a top view of the physical pin numbering.

Table 20. NCSI Connector

NCSI Connector				
Pin	Signal	I/O	Voltage	Description
1	RXER	O	3.3V	Enable signal from Rack Manager to HSC on the Server
2	GND	I	0V	Ground
3	TXD1	I	3.3V	Transmit Data from BMC to NIC

4	CLK_50M	I	0V	50Mhz Clock
5	TXD0	I	3.3V	Transmit Data from BMC to NIC
6	GND	I	0V	Ground
7	TXEN	I	3.3V	Transmit Enable from BMC to NIC
8	GND	I	0V	Ground
9	CRSDV	O	3.3V	Receive carrier sense and data valid from NIC to BMC
10	GND	I	0V	Ground
11	RXD1	O	3.3V	Receive Data from NIC to BMC
12	GND	I	0V	Ground
13	RXD0	O	3.3V	Receive Data from NIC to BMC
14	GND	I	0V	Ground

Figure 18. NCSI Connector Pin Numbering



10.14 USB 2.0 Internal Header

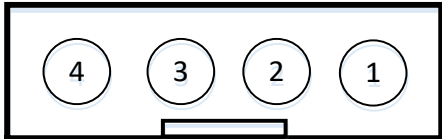
The motherboard supports a header connector for enabling USB 2.0 communication with the FPGA card. The connector is TE 440054-4 or equivalent. Table 21 describes the connector pinout.

Figure 19 shows a top view of the physical pin numbering.

Table 21. Internal USB Connector

Pin	Signal Name	I/O	Logic	Name/Description
1	P5_USB			5V (500mA max)
2	USB_N	I/O		USB Data
3	USB_P	I/O		USB Data
4	GND			Ground

Figure 19. Internal USB Connector Pinout



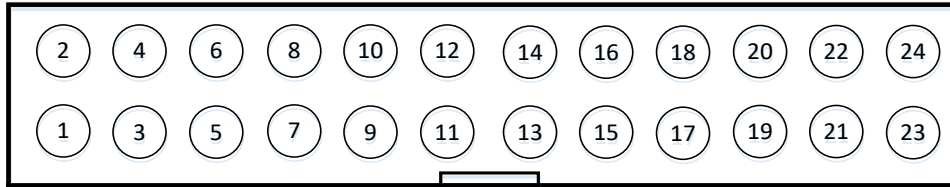
10.15 Fan Control Connector

The motherboard supports two header connectors for enabling fan control. The connectors are Molex 87831-2420 or equivalent. Table 22 describes the connector pinout. Figure 20 shows a top view of the physical pin numbering.

Table 22. Fan Control Connector

Server Management Connector				
Pin	Signal	I/O	Voltage	Description
1	FAN5_PWM	O	5V	Fan #5 PWM
2	FAN4_PWM	O	5V	Fan #4 PWM
3	FAN5_TACH	I	5V	Fan #5 Tachometer
4	FAN4_TACH	I	5V	Fan #4 Tachometer
5	P12V	O	12V	12V Fan Power
6	P12V	O	12V	12V Fan Power
7	GND	O	0V	Ground
8	GND	O	0V	Ground
9	FAN3_PWM	O	5V	Fan #3 PWM
10	FAN2_PWM	O	5V	Fan #2 PWM
11	FAN3_TACH	I	0V	Fan #3 Tachometer
12	FAN2_TACH	I	3.3V	Fan #2 Tachometer
13	P12V	I	3.3V	12V Fan Power
14	P12V	I	3.3V	12V Fan Power
15	GND	O	0V	Ground
16	GND	O	0V	Ground
17	FAN1_PWM	O	5V	Fan #1 PWM
18	FAN0_PWM	O	5V	Fan #0 PWM
19	FAN1_TACH	I	5V	Fan #1 Tachometer
20	FAN0_TACH	I	5V	Fan #0 Tachometer
21	P12V	O	12V	12V Fan Power
22	P12V	O	12V	12V Fan Power
23	GND	O	0V	Ground
24	GND	O	0V	Ground

Figure 20. Fan Control Connector Pin Numbering



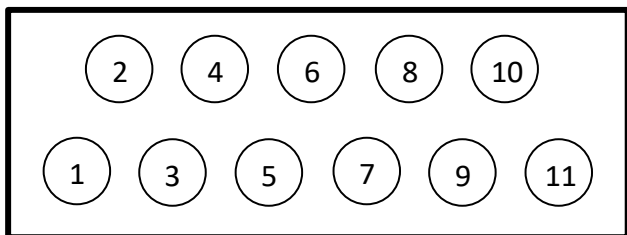
10.16 TPM Connector

The motherboard supports a header connector for interfacing to a TPM Module. The connector is FCI 91932-32111L or equivalent. Table 23 describes the connector pinout. Figure 21 shows a top view of the physical pin numbering. The TPM 2.0 module is connected to the CPU0 SPI bus.

Table 23. TPM Connector Pinout

TPM Connector				
Pin	Signal	I/O	Voltage	Description
1	SPI_CLK	O	3.3V	SPI Clock
2	RESET#	O	3.3V	Reset
3	SPI_MOSI	O	3.3V	SPI Data Out
4	SPI_MISO	I	3.3V	SPI Data In
5	SPI_CS#	O	3.3V	SPI Chip Select
6	I2C_SDA	I/O	3.3V	I2C Data
7	P3V3_STBY	O	3.3V	3.3V Standby Power
8	TPM_PRESENT#	I	3.3V	Indicates physical presence of TPM
9	SPI_IRQ#	I	3.3V	Interrupt
10	I2C_SCL	O	3.3V	I2C Clock
11	GND	O	0V	Ground

Figure 21. TPM Connector



10.17 Connector Quality

The Project Olympus System is designed for use in datacenters with a wide range of humidity. The connectors for these deployments are capable of withstanding high humidity during shipping and installation. The baseline for plating DIMMs and PCIe connectors is required to be 30u” thick gold. DIMM connectors are also required to include lubricant/sealant applied by the connector manufacturer that can remain intact after soldering and other manufacturing processes. The sealant is required to displace any voids in the connector gold plating.

11 Electrical Specifications

The following sections provide specifications for the motherboard input voltage and current.

11.1 Input Voltage, Power, and Current

Table 24 lists the nominal, maximum, and minimum values for the motherboard input voltage. The maximum and minimum voltages include the effects of connector temperature, age, noise/ripple, and dynamic loading.

Table 24. Input Power Requirements

	Minimum	Nominal	Max
Input voltage	11V DC	12.3V DC	14V DC
Input Power	n/a	n/a	750W
Inrush Rise Time	5ms	n/a	200ms

12V power to the motherboard is supplied through a 24 pin Mini-Fit Jr or equivalent connector. The motherboard provides inrush current control through the 12V bus rail; return-side inrush control is not used. The inrush current rises linearly from 0A to the load current over a minimum 5 millisecond (ms) period (this time period is no longer than 200ms).

11.2 Current Interrupt Protection and Power, Voltage, and Current Monitoring

The motherboard provides a cost-effective way to measure and report blade voltage and current consumption, and to make instance reporting available to the system. The motherboard supports power consumption measurements at the inrush controller. Accuracy of the measurement is +/- 1%.

The motherboard is capable of interrupting current flow within 1 microsecond (μ s) of exceeding the maximum current load.



11.3 Filtering and Capacitance

The motherboard provides sufficient input filtering and capacitance to support operation with the power supply as specified in the PSU Specification.

11.4 Grounding and Return

The server chassis grounding/return is provided to the motherboard from the tray assembly through the alignment and mounting holes that secure the motherboard to the tray. The motherboard is also tied to the PSU ground through the 12V power connector. Chassis ground and Logic ground are tied together on the motherboard.

12 Physical Specifications

The motherboard is fully compatible with the mechanical requirement of the Project Olympus Universal Motherboard Specification. The motherboard is intended to be deployable in a variety of server mechanical configurations. Figure 22 depicts the dimensions of an example motherboard. The front of the chassis is on the bottom side. The diagram below shows the locations of two PCIe x16 and one PCIe x32 slots on one motherboard as a reference. For detailed mechanical information including mounting hole location and dimensions, please reference the Project Olympus mechanical data package.

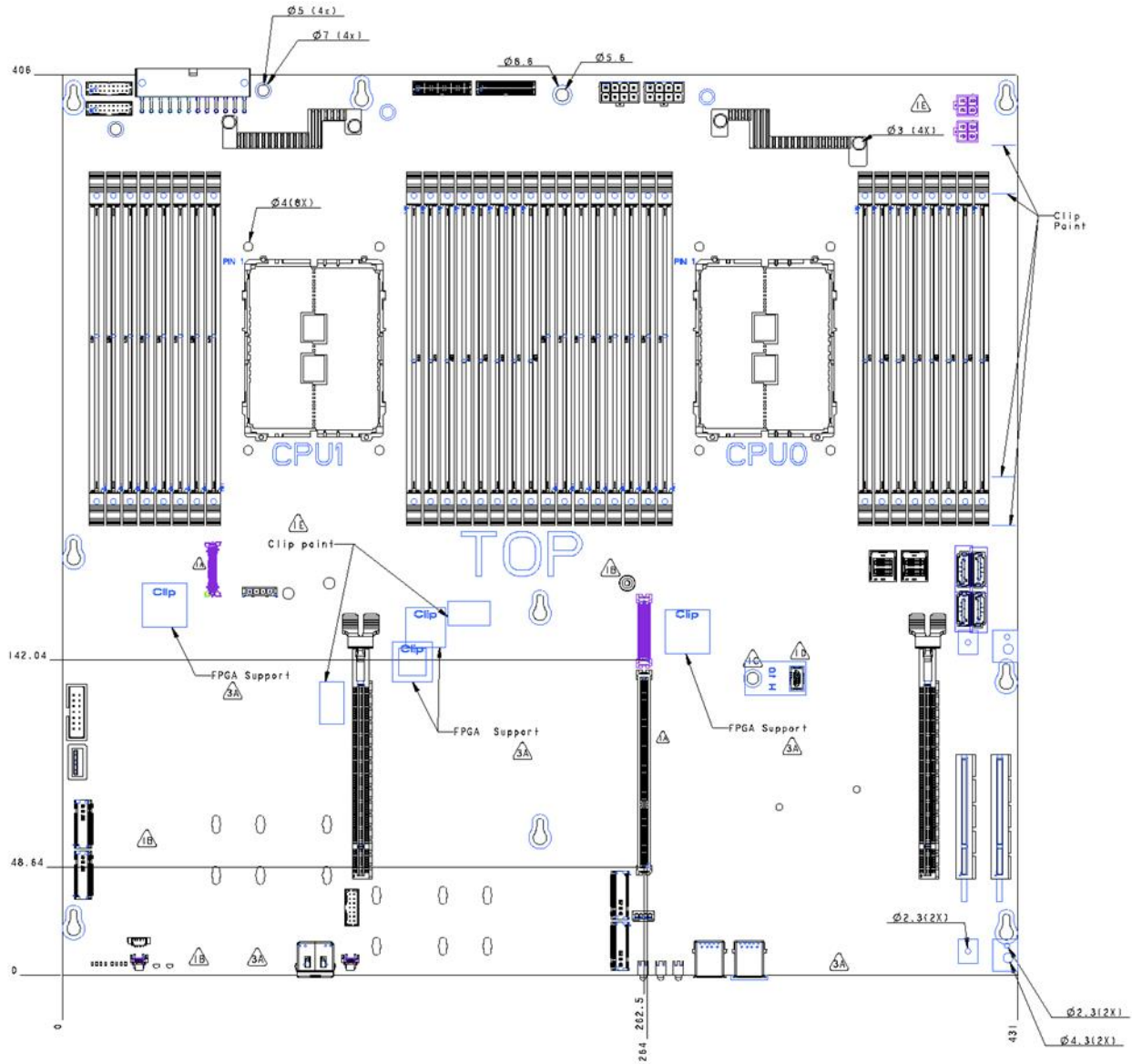


Figure 22. Example Motherboard Drawing

13 Environmental

The motherboard is designed to be deployed in an environmentally controlled location meeting the environmental requirements described in Table 25. The server must have the capability to provide full functional operation under the conditions given.

Table 25. Environmental Requirement

Specification		Requirement
Inlet temperature	Operating	<ul style="list-style-type: none"> • 50°F to 95°F (10°C to 35°C) • Maximum rate of change: 18°F (10°C)/hour • Allowable derating guideline of 1.6°F/1000ft (0.9°C/304m) above 3000 ft.
	Non-operating	<ul style="list-style-type: none"> • -40°F to 140°F (-40°C to 60°C) • Rate of change less than 36°F (20°C)/hour

14 Electromagnetic Interference Mitigation

Electromagnetic interference (EMI) containment, EMI shielding and grounding must be accounted for at the server assembly level.